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USB2649/USB2649I

1.0 OVERVIEW

The Microchip USB2649/USB2649I is an integrated USB 2.0 compliant, Hi-Speed hub for USB port expansion with an attached bulk only mass storage class peripheral controller. This multi-format flash media controller and USB Hub Combo features three downstream ports: one port is dedicated to an internally connected ultra fast flash media reader/writer and two exposed downstream ports are available for external peripheral expansion.

The Microchip USB2649/USB2649I is an ultra fast, OEM-configurable, hub controller IC with three downstream ports for embedded USB solutions. The USB2649/USB2649I will attach to an upstream port as a Full-Speed Hub or as a Full-/Hi-Speed Hub. The hub supports Low-Speed, Full-Speed, and Hi-Speed (if operating as a Hi-Speed Hub) downstream devices on all of the enabled downstream ports.

All required resistors on the USB ports are integrated into the hub. This includes all series termination resistors on D+ and D– pins and all required pull-down and pull-up resistors on D+ and D– pins. The over-current sense inputs for the downstream facing ports have internal pull-up resistors.

The USB2649/USB2649I includes programmable features such as:

PortMap which provides flexible port mapping and disable sequences. The downstream ports of a USB2649/USB2649I hub can be reordered or disabled in any sequence to support multiple platform designs with minimum effort. For any port that is disabled, the USB2649/USB2649I automatically reorders the remaining ports to match the USB host controller's port numbering scheme.

PortSwap which adds per-port programmability to USB differential-pair pin locations. PortSwap allows direct alignment of USB signals (D+/D–) to connectors avoiding uneven trace length or crossing of the USB differential signals on the PCB.

PHYBoost which enables four programmable levels of USB signal drive strength in downstream port transceivers. PHYBoost attempts to restore USB signal integrity that has been compromised by system level variables such as poor PCB layout, long cables, etc.

1.1 Device Features

1.1.1 Hardware Features

- Single chip flash media controller
- Transaction translator (TT) in the hub supports operation of FS and LS peripherals
- Full power management with individual or ganged power control of each downstream port
- Code execution via SPI ROM which must meet
 - 30 MHz or 60 MHz operation support
 - Single bit or dual bit mode support
 - Mode 0 or mode 3 SPI support

Compliant with the following flash media card specifications:

- Secure Digital 2.0 / MultiMediaCard 4.2
 - SD 2.0, HS-SD, HC-SD
 - TransFlash™ and reduced form factor media
 - 1/4/8 bit MMC 4.2
- MMC streaming mode support
- Memory Stick 1.43
- Memory Stick Pro Format 1.02
- Memory Stick Pro-HG Duo Format 1.01
 - Memory Stick, MS Duo, HS-MS, MS Pro-HG, MS Pro
- Memory Stick Duo 1.10
- xD-Picture Card 1.2 (USB2649 only)
- On board 24 MHz crystal driver circuit
- Optional external 24 MHz clock input
 - Must be used with an external resistor divider to provide a 1.8 V signal

- 8051 8-bit microprocessor
 - 60 MHz - single cycle execution
 - Boot ROM; 9 KB RAM
- Internal regulator for 1.8 V core operation
- Optimized pinout improves signal flow, easing implementation and allowing for improved signal integrity treatment

1.1.2 Software Features

- Optimized for low latency interrupt handling
- Hub and flash media reader/writer configuration via external SPI ROM
- EEPROM update via USB

1.2 OEM Selectable Features

1.2.1 Hub

A default configuration is available in USB2649/USB2649I following a reset. The USB2649/USB2649I may also be configured via external SPI ROM flash.

The USB2649/USB2649I supports several OEM selectable features:

- Compound Device support (port is permanently hardwired to a downstream USB peripheral device), on a port-by-port basis.
- Select over-current sensing and port power control on an individual (port-by-port) or ganged (all ports together) basis to match the OEM's choice of circuit board component selection.
- Port power control and over-current detection/delay features
- Configure the delay time for filtering the over-current sense inputs.
- Configure the delay time for turning on downstream port power.
- Bus- or self-powered selection
- Hub port disable or non-removable configurations
- Flexible port mapping and disable sequence. Ports can be disabled/reordered in any sequence to support multiple platforms with a single design. The hub will automatically reorder the remaining ports to match the host controller's numbering scheme.
- Programmable USB differential-pair pin location.
 - Eases PCB layout by aligning USB signal lines directly to connectors
- Programmable USB signal drive strength. Recover USB signal integrity due to compromised system environments using 4 levels of signal drive strength.
- Indicate the maximum current that the 2-port hub consumes from the USB upstream port.
- Indicate the maximum current required for the hub controller.

1.2.2 FLASH MEDIA CONTROLLER

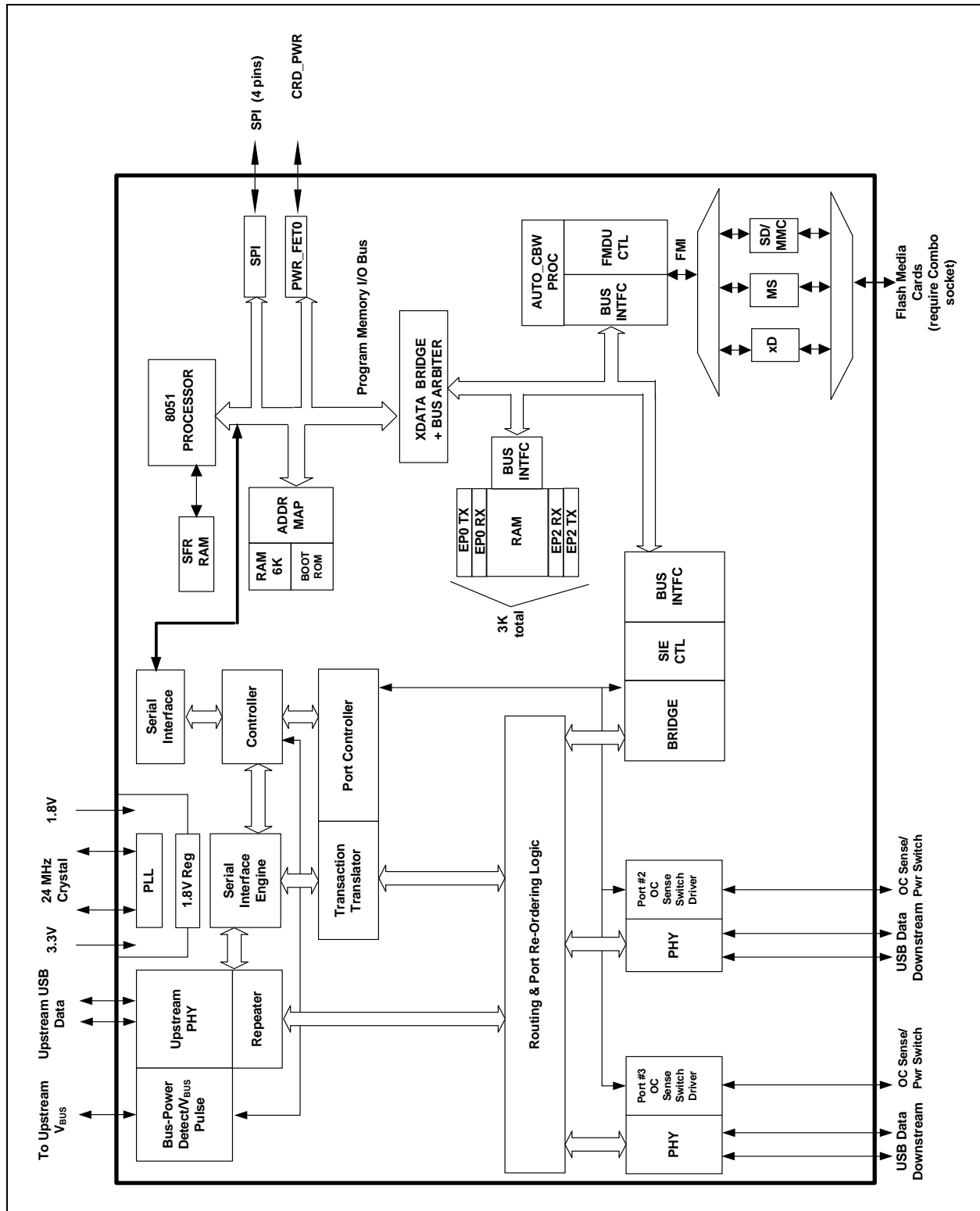
- Customize vendor ID, product ID, and device ID.
- 12-hex digit (max) serial number string
- Customizable vendor specific data
- 28-character manufacturer ID and product string for flash media reader/writer
- LED blink interval or duration

2.0 ACRONYMS

FM:	Flash Media
FMC:	Flash Media Controller
FS:	Full-speed Device
LS:	Low-speed Device
HS:	Hi-speed Device
MMC:	MultiMediaCard
MS:	Memory Stick
MSC:	Memory Stick Controller
OCS:	Over-current Sense
RXD:	Received eXchange Data
SD:	Secure Digital
SDC:	Secure Digital Controller
TXD:	Transmit eXchange Data
UART:	Universal Asynchronous Receiver-Transmitter
UCHAR:	Unsigned Character
UINT:	Unsigned Integer
xD:	xD-Picture Card

3.0 BLOCK DIAGRAM

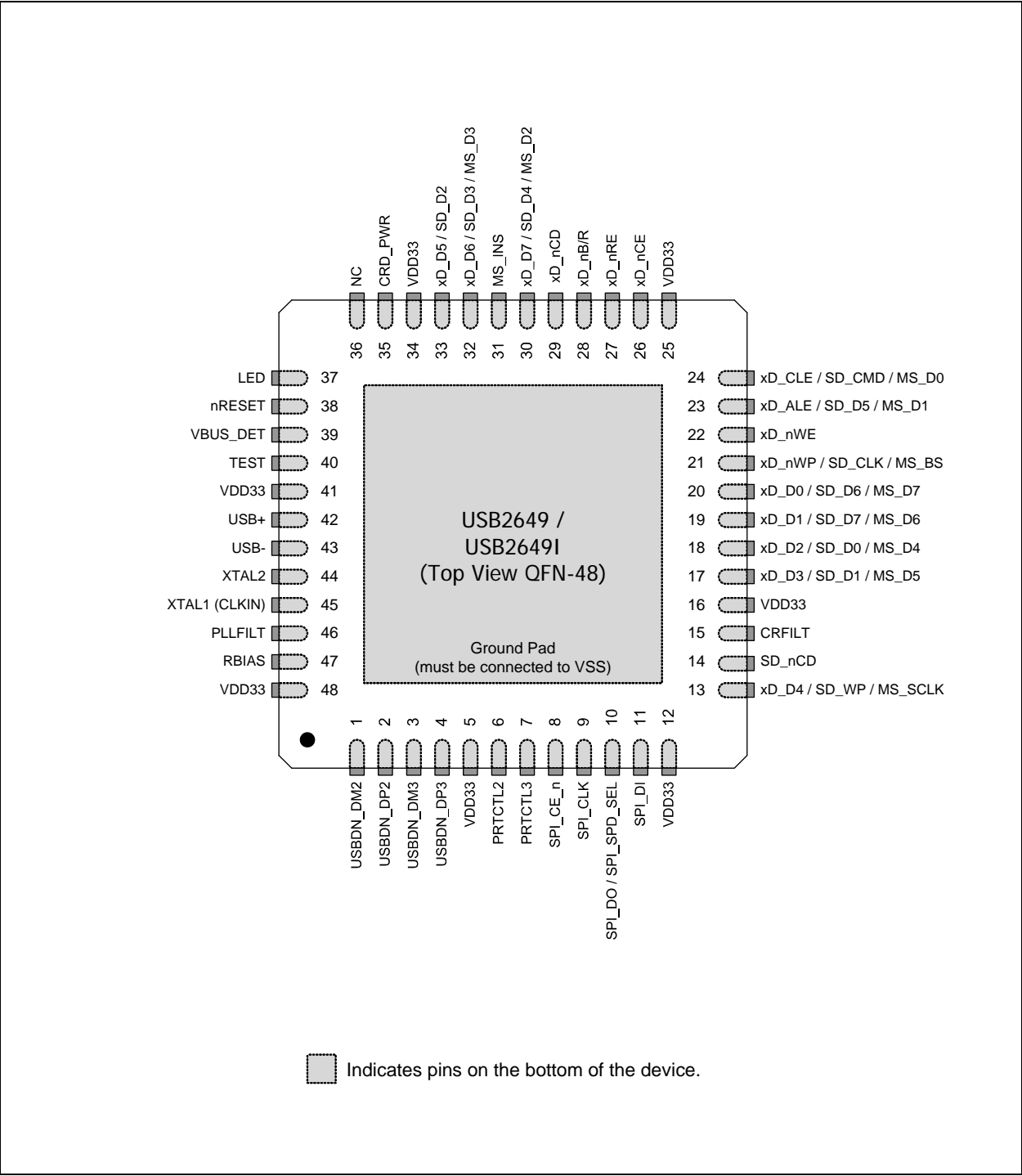
FIGURE 3-1: USB2649/USB2649I BLOCK DIAGRAM



USB2649/USB2649I

4.0 PIN CONFIGURATION

FIGURE 4-1: USB2649/USB2649I 48-PIN QFN



5.0 PIN TABLE

5.1 48-Pin Table

TABLE 5-1: USB2649/USB2649I 48-PIN TABLE

xD / SECURE DIGITAL / MEMORY STICK INTERFACE (18 PINS)			
xD_D3 / SD_D1 / MS_D5	xD_D2 / SD_D0 / MS_D4	xD_D1 / SD_D7 / MS_D6	xD_D0 / SD_D6 / MS_D7
xD_nWP / SD_CLK / MS_BS	xD_ALE / SD_D5 / MS_D1	xD_CLE / SD_CMD / MS_D0	xD_D7 / SD_D4 / MS_D2
xD_D6 / SD_D3 / MS_D3	xD_D5 / SD_D2	xD_nRE	xD_nWE
xD_D4 / SD_WP / MS_SCLK	xD_nB/R	xD_nCE	MS_INS
xD_nCD	SD_nCD		
USB INTERFACE (5 PINS)			
USB+	USB-	XTAL1 (CLKIN)	XTAL2
RBIAS			
2-PORT USB INTERFACE (7 PINS)			
USBDN_DP2	USBDN_DM2	PRTCTL2	PRTCTL3
USBDN_DP3	USBDN_DM3	VBUS_DET	
SPI INTERFACE (4 PINS)			
SPI_CE_n	SPI_CLK	SPI_DO/ SPI_SPD_SEL	SPI_DI
MISC (5 PINS)			
nRESET	TEST	LED	NC
CRD_PWR			
POWER AND GROUND (9 PINS)			
(7) VDD33	CRFILT	PLLFILT	
TOTAL 48			

USB2649/USB2649I

6.0 PIN DESCRIPTIONS

This section provides a detailed description of each signal. The signals are arranged in functional groups according to their associated interface. The pin descriptions below are applied when using the internal default firmware and can be referenced in [Section 7.0, "Configuration Options," on page 18](#). Please reference [Section 2.0, "Acronyms"](#) for a list of the acronyms used.

The “n” symbol in the signal name indicates that the active, or asserted, state occurs when the signal is at a low voltage level. When “n” is not present in the signal name, the signal is asserted at a high voltage level.

The terms assertion and negation are used exclusively. This is done to avoid confusion when working with a mixture of “active low” and “active high” signals. The term assert, or assertion, indicates that a signal is active, independent of whether that level is represented by a high or low voltage. The term negate, or negation, indicates that a signal is inactive.

6.1 USB2649/USB2649I Pin Descriptions

TABLE 6-1: USB2649/USB2649I PIN DESCRIPTIONS

Symbol	48-Pin QFN	Buffer Type (Table 6-2)	Description
xD-PICTURE CARD INTERFACE			
xD_D[7:0]	30 32 33 13 17 18 19 20	I/O12PU	xD-Picture Card Data 7-0 These pins are the bi-directional data signal xD_D7 - xD_D0 and have weak internal pull-up resistors.
xD_ALE	23	O12PD	xD-Picture Card Address Strobe This pin is an active high Address Latch Enable signal for the xD-Picture Card device. This pin has a weak pull-down resistor that is permanently enabled.
xD_nB/R	28	IPU	xD Busy or Data Ready This pin is connected to the BSY/RDY pin of the xD-Picture Card device. When using the internal FET, this pin has an internal weak pull-up resistor that is tied to the output of the internal power FET. If an external FET is used (the internal FET is disabled), then the internal pull-up is not available (an external pull-up is required).
xD_nCE	26	O12PU	xD Chip Enable This pin is an active low chip enable signal for the xD-Picture Card device. When using the internal FET, this pin has an internal weak pull-up resistor that is tied to the output of the internal power FET. If an external FET is used (the internal FET is disabled), then the internal pull-up is not available (an external pull-up is required).
xD_CLE	24	O12PD	xD-Picture Card Command Strobe This pin is an active high Command Latch Enable signal for the xD-Picture Card device. This pin has a weak pull-down resistor that is permanently enabled.
xD_nCD	29	I/O12	xD Card Detection Designates as the xD-Picture Card detection pin.

TABLE 6-1: USB2649/USB2649I PIN DESCRIPTIONS (CONTINUED)

Symbol	48-Pin QFN	Buffer Type (Table 6-2)	Description
xD_nRE	27	O12PU	<p>xD Read Enable</p> <p>This pin is an active low read strobe signal for the xD-Picture Card device.</p> <p>When using the internal FET, this pin has an internal weak pull-up resistor that is tied to the output of the internal power FET.</p> <p>If an external FET is used (the internal FET is disabled), then the internal pull-up is not available (an external pull-up is required).</p>
xD_nWE	22	O12PU	<p>xD Write Enable</p> <p>This pin is an active low write strobe signal for the xD-Picture Card device.</p> <p>When using the internal FET, this pin has an internal weak pull-up resistor that is tied to the output of the internal power FET.</p> <p>If an external FET is used (the internal FET is disabled), then the internal pull-up is not available (an external pull-up is required).</p>
xD_nWP	21	O12PD	<p>xD-Picture Card Write Protect</p> <p>This pin is an active low write protect signal for the xD-Picture Card device. This pin has a weak pull-down resistor that is permanently enabled.</p>
MEMORY STICK INTERFACE			
MS_BS	21	O12	<p>Memory Stick Bus State</p> <p>This pin is connected to the bus state pin of the MS device. It is used to control the Bus States 0, 1, 2, and 3 (BS0, BS1, and BS3) of the MS device.</p>
MS_INS	31	I/O12 IPU	<p>Memory Stick Card Insertion</p> <p>Designates as the Memory Stick card detection pin and has an internal weak pull-up resistor.</p>
MS_SCLK	13	O12	<p>Memory Stick System Clock</p> <p>This pin is an output clock signal to the MS device.</p>
MS_D[7:0]	20 19 17 18 32 30 23 24	I/O12PD	<p>Memory Stick System Data In/Out</p> <p>These pins are the bi-directional data signals for the MS device. In serial mode, the most significant bit (MSB) of each byte is transmitted first by either MSC or MS device on MS_D0.</p> <p>MS_D0, MS_D2, and MS_D3 have weak pull-down resistors. MS_D1 has a pull down resistor if in parallel mode, otherwise it is disabled. In 4- or 8-bit parallel modes, all MS_D7 - MS_D0 signals have weak pull-down resistors.</p>
SECURE DIGITAL / MULTIMEDIACARD INTERFACE			
SD_D[7:0]	19 20 23 30 32 33 17 18	I/O12PU	<p>Secure Digital Data 7-0</p> <p>These are the bi-directional data signals SD_D0-SD_D7 and have weak pull-up resistors.</p>

USB2649/USB2649I

TABLE 6-1: USB2649/USB2649I PIN DESCRIPTIONS (CONTINUED)

Symbol	48-Pin QFN	Buffer Type (Table 6-2)	Description
SD_CLK	21	O12	Secure Digital Clock This is an output clock signal to the SD/MMC device.
SD_CMD	24	I/O12PU	Secure Digital Command This is a bi-directional signal that connects to the CMD signal of the SD/MMC device and has an internal weak pull-up resistor.
SD_WP	13	I/O12	Secure Digital Write Protected Designates as the Secure Digital card mechanical write protect detect pin.
SD_nCD	14	I/O12	Secure Digital Card Detect Designates as the Secure Digital card detection pin.
USB INTERFACE			
USB- USB+	43 42	I/O-U	USB Bus Data These pins connect to the upstream USB bus data signals. USB+ and USB- can be swapped using the PortSwap feature (See Section 7.3.5.20, "F1h: Port Swap," on page 33).
USBDN_DM [3:2] USBDN_DP [3:2]	3 1 4 2	I/O-U	USB Bus Data These pins connect to the downstream USB bus data signals and can be swapped using the PortSwap feature (See Section 7.3.5.20, "F1h: Port Swap," on page 33).
PRTCTL[3:2]	7 6	I/OD12PU	USB Power Enable As an output, these pins enable power to downstream USB peripheral devices and have weak internal pull-up resistors. See Section 6.3, "Port Power Control" for diagram and usage instructions. As an input, when the power is enabled, these pins monitor the over-current condition. When an over-current condition is detected, the pins turn the power off.
VBUS_DET	39	I	Detect Upstream VBUS Power Detects the state of upstream VBUS power. The Hub monitors VBUS_DET to determine when to assert the internal D+ pull-up resistor (signaling a connect event). When designing a detachable hub, connect this pin to the VBUS power pin of the USB port that is upstream of the Hub. For self-powered applications with a permanently attached host, this pin should be pulled up, typically to VDD33. VBUS is a 3.3 volt input. A resistor divider must be used if connecting to 5 volts of USB power.
RBIAS	47	I-R	USB Transceiver Bias A 12.0 kΩ ±1.0% resistor is attached from VSS to this pin in order to set the transceiver's internal bias currents.
XTAL1 (CLKIN)	45	ICLKx	24 MHz Crystal Input or External clock Input This pin can be connected to one terminal of the crystal or it can be connected to an external 24 MHz 1.8 V clock when a crystal is not used.

TABLE 6-1: USB2649/USB2649I PIN DESCRIPTIONS (CONTINUED)

Symbol	48-Pin QFN	Buffer Type (Table 6-2)	Description
XTAL2	44	OCLKx	24 MHz Crystal Output This is the other terminal of the crystal, or it is left open when an external clock source is used to drive XTAL1(CLKIN).
SPI INTERFACE			
SPI_CE_n	8	O12	SPI Chip Enable This is the active low chip enable output. The SPI interface is permanently enabled and must be driven high in power down states.
SPI_CLK	9	I/O12	SPI Clock This is the SPI clock out to the serial ROM. See Section 6.4, "ROM BOOT Sequence" for diagram and usage instructions. During reset, drive this pin low.
SPI_DO / SPI_SPD_SEL	10	I/O12	SPI Data Out This is the data out for the SPI port. See Section 6.4, "ROM BOOT Sequence" for diagram and usage instructions. This pin is used to pick the speed of the SPI interface. During nRESET assertion, this pin will be tri-stated with the weak pull-down resistor enabled. When nRESET is negated, the value on the pin will be internally latched, and the pin will revert to SPI_DO functionality, the internal pull-down will be disabled. '0' = 30 MHz (No external resistor should be applied) '1' = 60 MHz (A 10 K external pull-up resistor must be applied) If the latched value is '1', then the pin is tri-stated when the chip is in the suspend state. If the latched value is '0', then the pin is driven low during a suspend state.
SPI_DI	11	I/O12PD	SPI Data In This is the data in to the controller from the ROM. This pin has a weak internal pull-down applied at all times to prevent floating.
MISC			
LED	37	I/O12	It can be used as media activities LED output.
NC	36		
CRD_PWR	35	I/O200	Card power drive: 3.3 V (100 mA or 200 mA) This pin powers the multiplexed flash media interface (slot) for xD, MS, and SD/MMC. If card power is not being used to power the multiplexed flash media interface, this pin may be used as a GPIO. It is a requirement for this to be the only FET used to power xD-Picture Card devices. Failure to do this will violate xD voltage specification on xD-Picture Card device pins. Bits 0, 1, 2, and 3 control FET 2 of Register A5h. Please reference Section 7.3.4.5, "A8h: LED Blink Interval (1 byte)," on page 25.
nRESET	38	IS	RESET Input The system uses this active low signal to reset the chip. The active low pulse should be at least 1 μ s wide.

USB2649/USB2649I

TABLE 6-1: USB2649/USB2649I PIN DESCRIPTIONS (CONTINUED)

Symbol	48-Pin QFN	Buffer Type (Table 6-2)	Description
TEST	40	I	TEST Input Tie this pin to ground for normal operation.
DIGITAL / POWER / GROUND			
CRFILT	15		VDD Core Regulator Filter Capacitor This pin must have a 1.0 μ F (or greater) $\pm 20\%$ (ESR $< 0.1 \Omega$) capacitor to VSS.
VDD33	5 12 16 25 34 41 48		3.3 V Power and Voltage Regulator Inputs Please refer to Section 9.0, "DC Parameters," on page 41 for more information. Pins 16 and 48 each require an external bypass capacitor of 4.7 μ F minimum.
PLLFILT	46		PLL Regulator Filter Capacitor This pin must have a 1.0 μ F (or greater) $\pm 20\%$ (ESR $< 0.1 \Omega$) capacitor to VSS.
VSS	ePad		The ground pad / ePad is the only VSS for the device and must be tied to ground with multiple vias.

6.2 Buffer Type Descriptions

TABLE 6-2: USB2649/USB2649I BUFFER TYPE DESCRIPTIONS

Buffer	Description
I	Input.
IPU	Input, weak internal pull-up.
IS	Input with Schmitt trigger.
I/O12	Input/output buffer with 12 mA sink and 12 mA source.
I/O200	Input/output buffer 12 mA with FET disabled, 100/200 mA source only when the FET is enabled.
I/O12PD	Input/output buffer with 12 mA sink and 12 mA source, with an internal weak pull-down resistor.
I/O12PU	Open drain, 12 mA sink with pull-up. Input with Schmitt trigger.
I/OD12PU	Input/open drain output buffer with a 12 mA sink.
O12	Output buffer with a 12 mA sink and a 12 mA source.
O12PD	Output buffer with 12 mA sink and 12 mA source, with a pull-down resistor.
O12PU	Output buffer with 12 mA sink and 12 mA source, with a pull-up resistor.
ICLKx	XTAL clock input.
OCLKx	XTAL clock output.
I/O-U	Analog input/output as defined in the USB 2.0 Specification.
I-R	RBIAS.

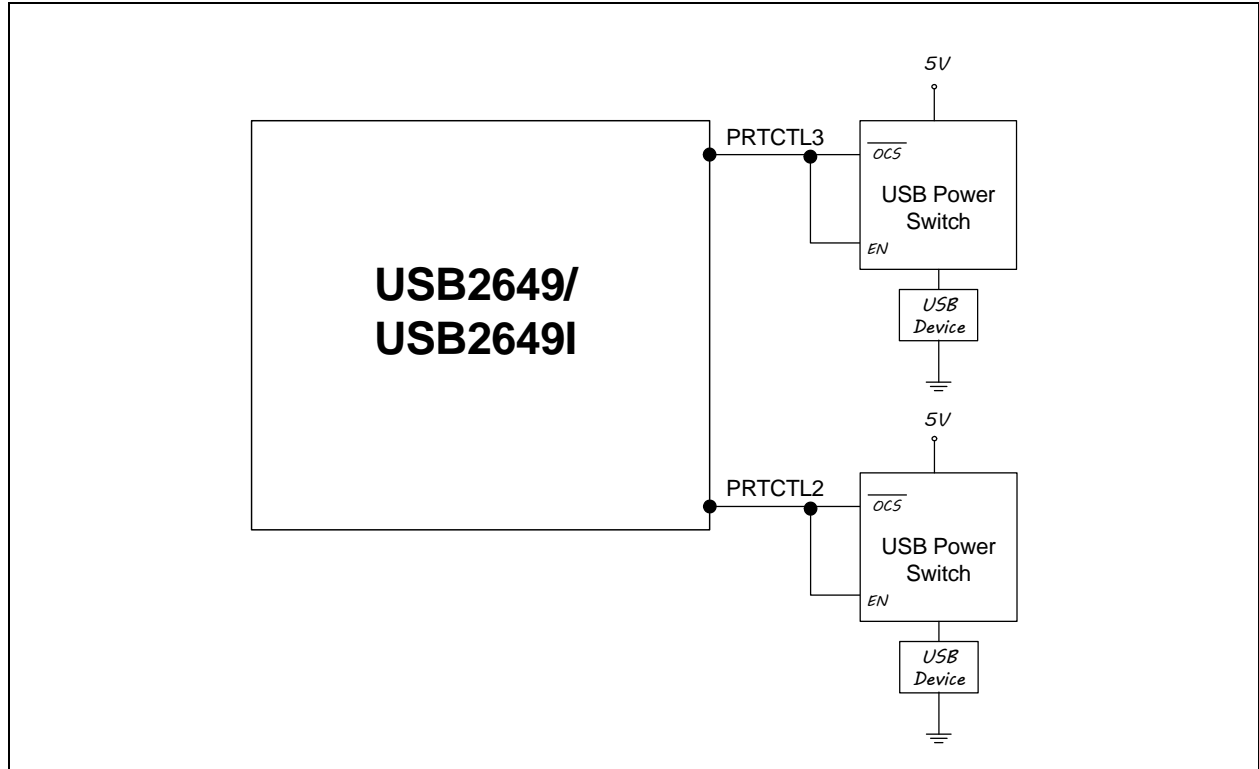
6.3 Port Power Control

6.3.1 PORT POWER CONTROL USING USB POWER SWITCH

The USB2649/USB2649I has a single port power control and over-current sense signal for each downstream port. When disabling port power, the driver will actively drive a '0'. To avoid unnecessary power dissipation, the internal pull-up resistor will be disabled at that time. When port power is enabled, the output driver is disabled, and the pull-up resistor

is enabled creating an open drain output. If there is an over-current situation, the USB Power Switch will assert the open drain OCS signal. The Schmitt trigger input will detect this event as a low. The open drain output does not interfere. The internal over-current sense filter handles the transient conditions, such as low voltage, while the device is powering up.

FIGURE 6-1: PORT POWER CONTROL WITH USB POWER SWITCH

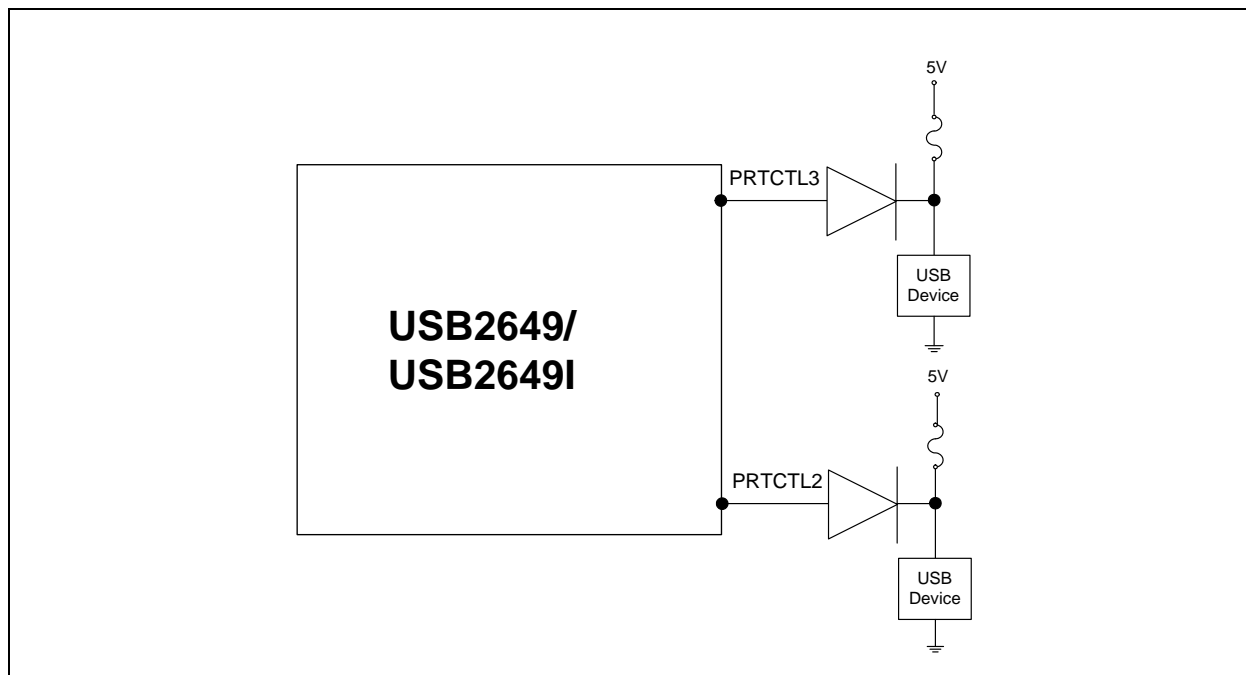


6.3.2 PORT POWER CONTROL USING A POLY FUSE

When using the USB2649/USB2649I with a poly fuse, an external diode must be used (See Figure 6-2). When disabling port power, the USB2649/USB2649I will drive a '0'. This procedure will have no effect since the external diode will isolate the pin from the load. When port power is enabled, the USB2649/USB2649I output driver is disabled, and the pull-up resistor is enabled which creates an open drain output. The open drain output condition means that the pull-up resistor is providing 3.3 volts to the anode of the diode. If there is an over-current situation, the poly fuse will open causing the cathode of the diode to go to 0 volts. The anode of the diode will be at 0.7 volt, and the Schmitt trigger input will register this as a low resulting in an over-current detection. The open drain output does not interfere.

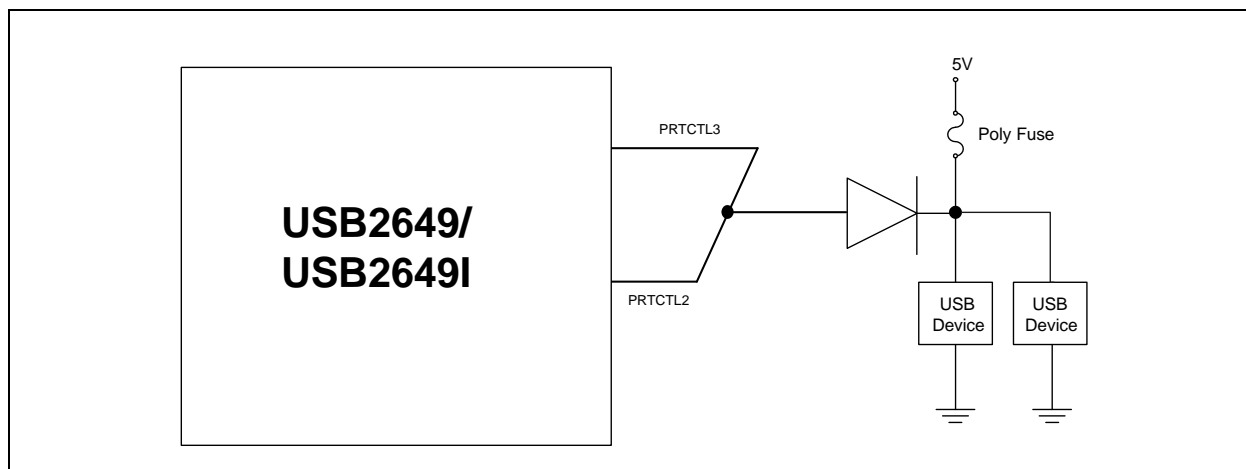
USB2649/USB2649I

FIGURE 6-2: PORT POWER CONTROL WITH SINGLE POLY FUSE AND MULTIPLE LOADS



When using a single poly fuse to power all devices, note that for the ganged situation, all power control pins must be tied together.

FIGURE 6-3: PORT POWER WITH GANGED CONTROL WITH POLY FUSE



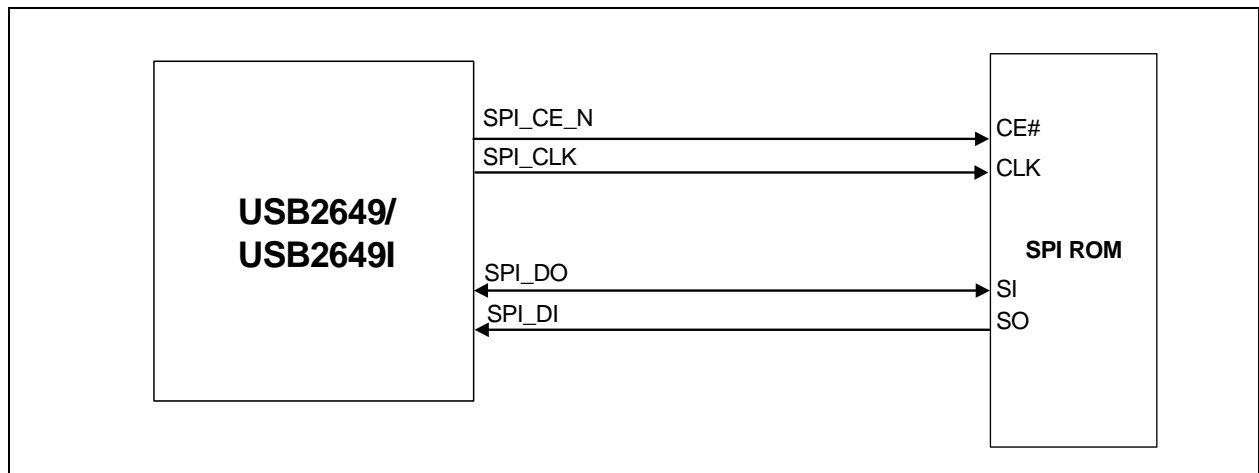
6.4 ROM BOOT Sequence

After power-on reset, the internal firmware checks for an external SPI flash device that contains a valid signature of "2DFU" beginning at address 0xFFFA. If a valid signature is found, then the external ROM is enabled and code execution begins at address 0x0000 in the external SPI device. Otherwise, the device enters device firmware upgrade (DFU) mode allowing the programming of the external SPI flash device.

The SPI ROM required for the USB2649/USB2649I must be 1 Mbit and support either 30 MHz or 60 MHz. The frequency used is set using the SPI_SPD_SEL. For 30 MHz operation, this pin must be pulled to ground through a 100 kΩ resistor. For 60 MHz operation, this pin must be pulled up through a 100 kΩ resistor. SPI_SPD_SEL: This pin is used to choose the speed of the SPI interface. During nRESET assertion, this pin will be tri-stated with the weak pull-down resistor enabled. When nRESET is negated, the value on the pin will be internally latched, and the pin will revert to SPI_DO functionality, the internal pull-down will be disabled.

The firmware can determine the speed of operation on the SPI port by checking the SPI_SPEED in the SPI_CTL register (0x2400 - RESET = 0x02). Both 1- and 2-bit SPI operation is supported. For optimum throughput, a 2-bit SPI ROM is recommended. Both mode 0 and mode 3 SPI ROMS are also supported.

FIGURE 6-4: USB2649/USB2649I SPI ROM CONNECTION



USB2649/USB2649I

7.0 CONFIGURATION OPTIONS

7.1 Hub

Microchip's USB 2.0 hub is fully compliant to the Universal Serial Bus Specification available from the USB Implementer's Forum found at <http://www.usb.org> (Revision 2.0 April 27, 2000 and the 12/7/2000 and 5/28/2002 Errata). Please reference Chapter 11 (Hub Specification) for general details regarding hub operation and functionality.

The hub provides 1 transaction translator (TT) that is shared by both downstream ports (defined as a single-TT configuration). The TT contains 4 non-periodic buffers.

7.1.1 HUB CONFIGURATION OPTIONS

The Microchip hub supports a large number of features (some are mutually exclusive), and must be configured in order to correctly function when attached to a USB host controller. There are two principal ways to configure the hub:

- via the internal default settings or
- by settings stored in an external EEPROM or SPI Flash device.

7.1.1.1 Power Switching Polarity

The hub only supports active high port power controllers.

7.1.2 VBUS DETECT

According to Section 7.2.1 of the USB 2.0 Specification, a downstream port cannot provide power to its D+ or D- pull-up resistors unless the upstream port's VBUS is in the asserted (powered) state. The VBUS_DET pin on the hub monitors the state of the upstream VBUS signal and will not pull-up the D+ resistor if VBUS is not active. If VBUS goes from an active to an inactive state (not powered), the hub will remove power from the D+ pull-up resistor within 10 seconds.

7.2 Card Reader

The Microchip USB2649/USB2649I is fully compliant with the following flash media card reader specifications:

- Secure Digital 2.0 / MultiMediaCard 4.2
 - SD 2.0, HS-SD, HC-SD
 - TransFlash™ and reduced form factor media
 - 1/4/8 bit MMC 4.2
- Memory Stick 1.43
- Memory Stick Pro Format 1.02
- Memory Stick Pro-HG Duo Format 1.01
 - Memory Stick, MS Duo, HS-MS, MS Pro-HG, MS Pro
- Memory Stick Duo 1.10
- xD-Picture Card 1.2 compliant

7.3 System Configurations

7.3.1 EEPROM/SPI INTERFACE

The USB2649/USB2649I can be configured via an external SPI ROM flash device containing the firmware for the USB2649/USB2649I. If an external configuration device does not exist, the internal default values will be used. If one of the external devices is used for configuration, the OEM can update the values through the USB interface. The hub will then “attach” to the upstream USB host.

When using an external SPI Flash, the register addresses in the following three tables ([Table 7-1](#), [Table 7-2](#), [Table 7-3](#)) refer to offsets from the starting location 'FE80h'.

The USBDM tool set is available in the USB264x Hub Card reader combo software release package. To download the software package from Microchip's website, please visit:

<http://www.microchip.com/SWLibraryWeb/producttc.aspx?product=USBDM%20Tool>

to go to the OBJ Hub Card Reader Software Download Agreement. Review the license, and if you agree, check the “I agree” box and then select “Confirm”. You will then be able to download the USB264x Hub Card reader combo release package zip file containing the USBDM tool set.

Please note that the following applies to the system values and descriptions when used:

- N/A = Not applicable to this part
- Reserved = For internal use

7.3.2 EEPROM DATA DESCRIPTOR

TABLE 7-1: INTERNAL FLASH MEDIA CONTROLLER CONFIGURATIONS

Address	Register Name	Description	Default Value
00h	USB_SER_LEN	USB Serial String Descriptor Length	1Ah
01h	USB_SER_TYP	USB Serial String Descriptor Type	03h
02h-19h	USB_SER_NUM	USB Serial Number	"000000264001" (See Note 7-1)
1Ah-1Bh	USB_VID	USB Vendor Identifier	0424
1Ch-1Dh	USB_PID	USB Product Identifier	4050
1Eh	USB_LANG_LEN	USB Language String Descriptor Length	04h
1Fh	USB_LANG_TYP	USB Language String Descriptor Type	03h
20h	USB_LANG_ID_LSB	USB Language Identifier Least Significant Byte	09h (See Note 7-3)
21h	USB_LANG_ID_MSB	USB Language Identifier Most Significant Byte	04h (See Note 7-3)
22h	USB_MFR_STR_LEN	USB Manufacturer String Descriptor Length	10h
23h	USB_MFR_STR_TYP	USB Manufacturer String Descriptor Type	03h
24h-31h	USB_MFR_STR	USB Manufacturer String	"Generic" (See Note 7-1)
32h-5Dh	Reserved	-	00h
5Eh	USB_PRD_STR_LEN	USB Product String Descriptor Length	30h
5Fh	USB_PRD_STR_TYP	USB Product String Descriptor Type	03h
60h-99h	USB_PRD_STR	USB Product String	"Ultra Fast Media Reader" (See Note 7-1)
9Ah	USB_BM_ATT	USB BmAttribute	80h
9Bh	USB_MAX_PWR	USB Max Power	30h (96 mA)
9Ch	ATT_LB	Attribute Lo byte	40h (Reverse SD_WP only)
9Dh	ATT_HLB	Attribute Hi Lo byte	00h
9Eh	ATT_LHB	Attribute Lo Hi byte	00h
9Fh	ATT_HB	Attribute Hi byte	00h
A0h	MS_PWR_LB	Memory Stick Device Power Lo byte	08h
A1h	MS_PWR_HB	Memory Stick Device Power Hi byte	00h
A2h	Not Applicable	-	80h
A3h	Not Applicable	-	00h
A4h	SM_PWR_LB	Smart Media Device Power Lo byte	00h (See Note 7-2)
A5h	SM_PWR_HB	Smart Media Device Power Hi byte	08h (See Note 7-2)

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TABLE 7-1: INTERNAL FLASH MEDIA CONTROLLER CONFIGURATIONS (CONTINUED)

Address	Register Name	Description	Default Value
A6h	SD_PWR_LB	Secure Digital Device Power Lo byte	00h
A7h	SD_PWR_HB	Secure Digital Device Power Hi byte	80h
A8h	LED_BLK_INT	LED Blink Interval	02h
A9h	LED_BLK_DUR	LED Blink After Access	28h
AAh - B0h	DEV0_ID_STR	Device 0 Identifier String	"COMBO"
B1h - B7h	DEV1_ID_STR	Device 1 Identifier String	N/A
B8h - BEh	DEV2_ID_STR	Device 2 Identifier String	N/A
BFh - C5h	DEV3_ID_STR	Device 3 Identifier String	N/A
C6h - CDh	INQ_VEN_STR	Inquiry Vendor String	"Generic"
CEh - D2h	INQ_PRD_STR	Inquiry Product String	2640
D3h	DYN_NUM_LUN	Dynamic Number of LUNs	FFh
D4h - D7h	LUN_DEV_MAP	Device to LUN Mapping	FFh, FFh, FFh, FFh
D8h - DAh	Reserved	-	00h, 04h, 09h
DBh - DDh	Reserved	-	5Ch, 59h, 9Ah

TABLE 7-2: HUB CONTROLLER CONFIGURATIONS

Address	Register Name	Description	Default Value
DEh	VID_LSB	Vendor ID Least Significant Byte	24h
DFh	VID_MSB	Vendor ID Most Significant Byte	04h
E0h	PID_LSB	Product ID Least Significant Byte	40h
E1h	PID_MSB	Product ID Most Significant Byte	26h
E2h	DID_LSB	Device ID Least Significant Byte	00h
E3h	DID_MSB	Device ID Most Significant Byte	00h
E4h	CFG_DAT_BYT1	Configuration Data Byte 1	8Bh
E5h	CFG_DAT_BYT2	Configuration Data Byte 2	28h
E6h	CFG_DAT_BYT3	Configuration Data Byte 3	00h
E7h	NR_DEVICE	Non-Removable Devices	02h
E8h	PORT_DIS_SP	Port Disable (Self)	00h
E9h	PORT_DIS_BP	Port Disable (Bus)	00h
EAh	MAX_PWR_SP	Max Power (Self)	01h
EBh	MAX_PWR_BP	Max Power (Bus)	32h
ECh	HC_MAX_C_SP	Hub Controller Max Current (Self)	01h
EDh	HC_MAX_C_BP	Hub Controller Max Current (Bus)	32h
EEh	PWR_ON_TIME	Power-on Time	32h
EFh	BOOST_UP	Boost_Up	00h
F0h	BOOST_3:0	Boost_3:0	00h
F1h	PRT_SWP	Port Swap	00h
F2h	PRTM12	Port Map 12	00h
F3h	PRTM3	Port Map 3	00h

TABLE 7-3: OTHER INTERNAL CONFIGURATIONS

Address	Register Name	Description	Default Value
F4h	Reserved	-	00h
F5h	Reserved	-	66h
F6-FBh	Reserved	-	00h
FCh-FFh	NVSTORE_SIG	Non-volatile storage signature ("ATA2")	"ATA2"

Note 7-1 This value is a UNICODE UTF-16LE encoded string value that meets the USB 2.0 Specification (Revision 2.0, 2000). Values in double quotations without this note are ASCII values.

Note 7-2 A value of "SM" will be overridden with "xD" once an xD-Picture Card has been identified.

Note 7-3 For a list of the most current 16-bit language ID's defined by the USB-IF, please visit <http://www.unicode.org> or consult *The Unicode Standard, Worldwide Character Encoding*, (Version 4.0), The Unicode Consortium, Addison-Wesley Publishing Company, Reading, Massachusetts.

7.3.3 EEPROM DATA DESCRIPTOR REGISTER DESCRIPTIONS

7.3.3.1 00h: USB Serial String Descriptor Length

Byte	Name	Description
0	USB_SER_LEN	USB serial string descriptor length as defined by Section 9.6.7 "String" of the USB 2.0 Specification (Revision 2.0, 2000). This field is the "bLength" which describes the size of the string descriptor (in bytes).

7.3.3.2 01h: USB Serial String Descriptor Type

Byte	Name	Description
1	USB_SER_TYP	USB serial string descriptor type as defined by Section 9.6.7 "String" of the USB 2.0 Specification (Revision 2.0, 2000). This field is the "bDescriptorType" which is a constant value associated with a string descriptor type.

7.3.3.3 02h-19h: USB Serial Number Option

Byte	Name	Description
25:2	USB_SER_NUM	Maximum string length is 12 hex digits. Must be unique to each device.

7.3.3.4 1Ah-1Bh: USB Vendor Identifier Option

Byte	Name	Description
1:0	USB_VID	This ID is unique for every vendor. The vendor ID is assigned by the USB Implementer's Forum.

7.3.3.5 1Ch-1Dh: USB Product Identifier Option

Byte	Name	Description
1:0	USB_PID	This ID is unique for every product. The product ID is assigned by the vendor.

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7.3.3.6 1Eh: USB Language String Descriptor Length

Byte	Name	Description
0	USB_LANG_LEN	USB serial string descriptor length as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bLength” which describes the size of the string descriptor (in bytes).

7.3.3.7 1Fh: USB Language String Descriptor Type

Byte	Name	Description
1	USB_LANG_TYP	USB serial string descriptor type as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bDescriptorType” which is a constant value associated with a string descriptor type.

7.3.3.8 20h: USB Language Identifier Least Significant Byte

Byte	Name	Description
2	USB_LANG_ID_LSB	English Language Code = '0409'. See Note 7-3 to reference additional language ID's defined by the USB-IF.

7.3.3.9 21h: USB Language Identifier Most Significant Byte

Byte	Name	Description
3	USB_LANG_ID_MSB	English Language Code = '0409'. See Note 7-3 to reference additional language ID's defined by the USB-IF.

7.3.3.10 22h: USB Manufacturer String Descriptor Length

Byte	Name	Description
0	USB_MFR_STR_LEN	USB serial string descriptor length as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bLength” which describes the size of the string descriptor (in bytes).

7.3.3.11 23h: USB Manufacturer String Descriptor Type

Byte	Name	Description
1	USB_MFR_STR_TYP	USB serial string descriptor type as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bDescriptorType” which is a constant value associated with a string descriptor type.

7.3.3.12 24h-31h: USB Manufacturer String

Byte	Name	Description
15:2	USB_MFR_STR	Maximum string length is 28 characters. (See Note 7-4)

7.3.3.13 32h-5Dh: Reserved

Byte	Name	Description
59:16	Reserved	Reserved.

7.3.3.14 5Eh: USB Product String Descriptor Length

Byte	Name	Description
0	USB_PRD_STR	USB serial string descriptor length as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bLength” which describes the size of the string descriptor (in bytes).

7.3.3.15 5Fh: USB Product String Descriptor Type

Byte	Name	Description
1	USB_PRD_STR	USB serial string descriptor type as defined by Section 9.6.7 “String” of the USB 2.0 Specification (Revision 2.0, 2000). This field is the “bDescriptorType” which is a constant value associated with a string descriptor type.

7.3.3.16 60h-99h: USB Product String

Byte	Name	Description
59:2	USB_PRD_STR	This string will be used during the USB enumeration process in the Windows operating system. Maximum string length is 28 characters. (See Note 7-4)

Note 7-4 While the full strings are reported during USB enumeration, Windows XP/Vista reads concatenated version of the strings from the standard SCSI inquiry response when storing the values for display in the Windows registry and device manager.

7.3.3.17 9Ah: USB BmAttribute (1 byte)

Byte	Name	Description
7:0	USB_BM_ATT	<p>Self- or Bus-Power: Selects between self- and bus-powered operation.</p> <p>The hub is either self-powered (draws less than 2 mA of upstream bus power) or bus-powered (limited to a 100 mA maximum of upstream power prior to being configured by the host controller).</p> <p>When configured as a bus-powered device, the Microchip hub consumes less than 100 mA of current prior to being configured. After configuration, the bus-powered Microchip hub (along with all associated hub circuitry, any embedded devices if part of a Compound Device, and 100 mA per externally available downstream port) must consume no more than 500 mA of upstream VBUS current. The current consumption is system dependent, and the OEM must ensure that the USB 2.0 Specification is not violated.</p> <p>When configured as a self-powered device, <1 mA of upstream VBUS current is consumed and all ports are available, with each port being capable of sourcing 500 mA of current.</p> <p>80 = Bus-powered operation (default) C0 = Self-powered operation A0 = Bus-powered operation with remote wake-up E0 = Self-powered operation with remote wake-up</p>

7.3.3.18 9Bh: USB MaxPower (1 byte)

Byte	Name	Description
7:0	USB_MAX_PWR	USB Max Power per the USB 2.0 Specification. Do NOT set this value greater than 100 mA.

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7.3.3.19 9Ch-9Fh: Attribute Byte Descriptions

Byte	Byte Name	Bit	Description
0	ATT_LB	3:0	Always reads '0'.
		4	Inquire Manufacturer and Product ID Strings '1' - Use the Inquiry Manufacturer and Product ID Strings. '0' (default) - Use the USB Descriptor Manufacturer and Product ID Strings.
		5	Always reads '0'.
		6	Reverse SD Card Write Protect Sense '1' (default) - SD cards will be write protected when SW_nWP is high, and writable when SW_nWP is low. '0' - SD cards will be write protected when SW_nWP is low, and writable when SW_nWP is high.
		7	Reserved
1	ATT_HLB	3:0	Always reads '0'.
		4	Activity LED True polarity '1' - Activity LED to Low True. '0' (default) - Activity LED polarity to High True.
		5	Common Media Insert / Media Activity LED '1' - The activity LED will function as a common media inserted/media access LED. '0' (default) - The activity LED will remain in its idle state until media is accessed.
		7:6	Always reads '0'.
2	ATT_LHB	0	Attach on Card Insert / Detach on Card Removal '1' - Attach on Insert is enabled. '0' (default) - Attach on Insert is disabled.
		1	Always reads '0'.
		2	Enable Device Power Configuration '1' - Custom Device Power Configuration stored in the NVSTORE is used. '0' (default) - Default Device Power Configuration is used.
		7:3	Always reads '0'.
3	ATT_HB	6:0	Always reads '0'.
		7	xD Player Mode

7.3.4 A0H-A7H: DEVICE POWER CONFIGURATION

The USB4640/USB4640i has one internal FET which can be utilized for card power. This section describes the internal default configuration. The settings are stored in NVSTORE and provide the following features:

1. A card can be powered by an external FET or by an internal FET.
2. The power limit can be set to 100 mA or 200 mA (Default) for the internal FET.

Each media uses two bytes to store its device power configuration. Bit 3 selects between internal or external card power FET options. For internal FET card power control, bits 0 through 2 are used to set the power limit. The "Device Power Configuration" bits are ignored unless the "Enable Device Power Configuration" bit is set. See [Section 7.3.3.19, "9Ch-9Fh: Attribute Byte Descriptions," on page 24](#).

7.3.4.1 A0h-A1h: Memory Stick Device Power

FET	Type	Bits	Bit Type	Description
0	FET Lo Byte MS_PWR_LB	3:0	Low Nibble	0000b Disabled
1		7:4	High Nibble	
2	FET Hi Byte MS_PWR_HB	3:0	Low Nibble	0000b Disabled 0001b External FET enabled 1000b Internal FET with 100 mA power limit 1010b Internal FET with 200 mA power limit
3		7:4	High Nibble	0000b Disabled

7.3.4.2 A2h-A3h: Not Applicable

Byte	Name	Description
1:0	Not Applicable	Not applicable to USB2649/USB2649I.

7.3.4.3 A4h-A5h: Smart Media Device Power

FET	Type	Bits	Bit Type	Description
0	FET Lo Byte SM_PWR_LB	3:0	Low Nibble	0000b Disabled
1		7:4	High Nibble	
2	FET Hi Byte SM_PWR_HB	3:0	Low Nibble	0000b Disabled 0001b External FET enabled 1000b Internal FET with 100 mA power limit 1010b Internal FET with 200 mA power limit
3		7:4	High Nibble	0000b Disabled

7.3.4.4 A6h-A7h: Secure Digital/MultiMediaCard Device Power

FET	Type	Bits	Bit Type	Description
0	FET Lo Byte SD_PWR_LB	3:0	Low Nibble	0000b Disabled
1		7:4	High Nibble	
2	FET Hi Byte SD_PWR_HB	3:0	Low Nibble	0000b Disabled 0001b External FET enabled 1000b Internal FET with 100 mA power limit 1010b Internal FET with 200 mA power limit
3		7:4	High Nibble	0000b Disabled

7.3.4.5 A8h: LED Blink Interval (1 byte)

Byte	Name	Description
0	LED_BLK_INT	The blink rate is programmable in 50 ms intervals. Bit 7 indicates an idle state: '0' - Off '1' - On Bits 0-6 are used to determine the blink interval up to a max of 128 x 50 ms.

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7.3.4.6 A9h: LED Blink Duration (1 byte)

Byte	Name	Description
1	LED_BLK_DUR	LED blink After Access. This byte is used to designate the number of seconds that the LED will continue to blink after a drive access. Setting this byte to "05" will cause the LED to blink for 5 seconds after a drive access.

7.3.4.7 AAh-B0h: Device 0 Identifier String

Byte	Name	String	Description
6:0	DEV0_ID_STR	"COMBO"	MS, SM, and SD/MMC are mapped to device 0 identifier string because USB2649/USB2649I only supports one LUN. When applicable, the "SM" value will be overridden with xD once an xD-Picture Card has been identified.

7.3.4.8 B1h-C5h: Not Applicable

Byte	Name	Description
20:0	Not Applicable	Not applicable to USB2649/USB2649I.

7.3.4.9 C6h-CDh: Inquiry Vendor String

Byte	Name	String	Description
7:0	INQ_VEN_STR	"Generic"	If bit 4 of the 1st attribute byte is set, the device will use these strings in response to a USB inquiry command, instead of the USB Descriptor Manufacturer and Product ID Strings.

7.3.4.10 CEh-D2h: Inquiry Product String

Byte	Name	Unit	Description
4:0	INQ_PRD_STR	2640	If bit 4 of the 1st attribute byte is set, the device will use these strings in response to a USB inquiry command, instead of the USB Descriptor Manufacturer and Product ID Strings.

7.3.4.11 D3h: Dynamic Number of LUNs

Bit	Byte Name	UCHAR	Description
7:0	DYN_NUM_LUN	FFh	<p>These bytes are used to specify the number of LUNs the device exposes to the host. These bytes are also used for icon sharing by assigning more than one LUN to a single icon. This is used in applications where the device utilizes a combo socket and the OEM wishes to have only a single icon displayed for one or more interfaces.</p> <p>USB2649/USB2649I supports one LUN. MS, SM, and SD/MMC are mapped to that LUN.</p> <p>If this field is set to "FF", the program assumes that you are using the default value of "04" and will display icons for xD, MS, and SD/MMC. If this field is any other value besides "FF", you must specify the LUN# assignments in the boxes starting with LUN 00 and going to (# of Icons to Display -1).</p> <p>These bytes are reserved for internal use only.</p>

7.3.4.12 D4h-D7h: Device to LUN Mapping

Byte	Name	UCHARS	Description
3:0	DEV_LUN_MAP	FFh, FFh, FFh, FFh	<p>These bytes are used to specify the number of LUNs the device exposes to the host. These bytes are also used for icon sharing by assigning more than one LUN to a single icon. This is used in applications where the device utilizes a combo socket and the OEM wishes to have only a single icon displayed for one or more interfaces.</p> <p>USB2649/USB2649I supports one LUN. MS, SM, and SD/MMC are mapped to that LUN.</p> <p>If this field is set to "FF", the program assumes that you are using the default value of "04" and will display icons for xD, MS, and SD/MMC. If this field is any other value besides "FF", you must specify the LUN# assignments in the boxes starting with LUN 00 and going to (# of Icons to Display -1).</p> <p>These bytes are reserved for internal use only.</p>

7.3.4.13 D8h-DDh: Reserved

Bit	Byte Name	Description
5:0	Reserved	For internal use only.

7.3.5 HUB CONTROLLER CONFIGURATIONS

7.3.5.1 DEh: Vendor ID (LSB)

Bit	Byte Name	Description
7:0	VID_LSB	Least Significant Byte of the Vendor ID. This is a 16-bit value that uniquely identifies the Vendor of the user device (assigned by USB Implementer's Forum).

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7.3.5.2 DFh: Vendor ID (MSB)

Bit	Byte Name	Description
7:0	VID_MSB	Most Significant Byte of the Vendor ID. This is a 16-bit value that uniquely identifies the Vendor of the user device (assigned by USB Implementer's Forum).

7.3.5.3 E0h: Product ID (LSB)

Bit	Name	Description
7:0	PID_LSB	Least Significant Byte of the Product ID. This is a 16-bit value that the vendor can assign that uniquely identifies this particular product.

7.3.5.4 E1h: Product ID (MSB)

Bit	Name	Description
7:0	PID_MSB	Most Significant Byte of the Product ID. This is a 16-bit value that the vendor can assign that uniquely identifies this particular product.

7.3.5.5 E2h: Device ID (LSB)

Bit	Name	Description
7:0	DID_LSB	Least Significant Byte of the Device ID. This is a 16-bit device release number in BCD (binary coded decimal) format.

7.3.5.6 E3h: Device ID (MSB)

Bit	Name	Description
7:0	DID_MSB	Most Significant Byte of the Device ID. This is a 16-bit device release number in binary coded decimal (BCD) format.

7.3.5.7 E4h: Configuration Data Byte 1 (CFG_DAT_BYT1)

Bit	Name	Description
7	SELF_BUS_PWR	<p>Self- or Bus-Power: Selects between self- and bus-powered operation.</p> <p>The hub is either self-powered (draws less than 2 mA of upstream bus power) or bus-powered (limited to a 100 mA maximum of upstream power prior to being configured by the host controller).</p> <p>When configured as a bus-powered device, the Microchip hub consumes less than 100 mA of current prior to being configured. After configuration, the bus-powered Microchip hub (along with all associated hub circuitry, any embedded devices if part of a Compound Device, and 100 mA per externally available downstream port) must consume no more than 500 mA of upstream VBUS current. The current consumption is system dependent, and the OEM must ensure that the USB 2.0 Specification is not violated.</p> <p>When configured as a self-powered device, <1 mA of upstream VBUS current is consumed and all ports are available, with each port being capable of sourcing 500 mA of current.</p> <p>'0' = Bus-powered operation '1' = Self-powered operation</p>
6	Reserved	Always reads '0'.

Bit	Name	Description
5	HS_DISABLE	Hi-Speed Disable: Disables the capability to attach as either a Hi-/Full-Speed device, and forces attachment as Full-Speed only (i.e. no Hi-Speed support). '0' = Hi-/Full-Speed '1' = Full-Speed-Only (Hi-Speed disabled!)
4	Reserved	Always reads '0'.
3	EOP_DISABLE	EOP Disable: Disables EOP generation of EOF1 when in Full-Speed mode. During FS operation only, this permits the hub to send EOP if no downstream traffic is detected at EOF1. See Section 11.3.1 of the USB 2.0 Specification for additional details. Note: generation of an EOP at the EOF1 point may prevent a Host Controller (operating in FS mode) from placing the USB bus in suspend. '0' = An EOP is generated at the EOF1 point if no traffic is detected. '1' = EOP generation at EOF1 is disabled (Note: This is normal USB operation). Note: This is a rarely used feature in the PC environment, existing drivers may not have been thoroughly debugged with this feature enabled. It is included because it is a permitted feature in Chapter 11 of the USB 2.0 Specification.
2:1	CURRENT_SNS	Over-Current Sense: Selects current sensing on a port-by-port basis, all ports ganged, or none (only for bus-powered hubs). The ability to support current sensing on a port or ganged basis is dependent upon the hardware implementation. '00' = Ganged sensing (all ports together) '01' = Individual port-by-port '1x' = Over-current sensing not supported (must only be used with bus-powered configurations!)
0	PORT_PWR	Port Power Switching: Enables power switching on all ports simultaneously (ganged), or port power is individually switched on and off on a port-by-port basis (individual). The ability to support power enabling on a port or ganged basis is dependent upon the hardware implementation. '0' = Ganged switching (all ports together) '1' = Individual port-by-port switching

7.3.5.8 E5h: Configuration Data Byte 2 (CFG_DAT_BYT2)

Bit	Name	Description
7:6	Reserved	Always reads '0'.
5:4	OC_TIMER	OverCurrent Timer: Over-current Timer delay. 00 = 50 ns 01 = 100 ns 10 = 200 ns 11 = 400 ns
3	COMPOUND	Compound Device: Allows OEM to indicate that the hub is part of a compound (see the USB 2.0 Specification for definition) device. The applicable port(s) must also be defined as having a "non-removable device". When configured via strapping options, declaring a port as non-removable automatically causes the hub controller to report that it is part of a Compound Device. '0' = No '1' = Yes, the hub is part of a Compound Device
2:0	Always reads '0'.	Always reads '0'.

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7.3.5.9 E6h: Configuration Data Byte 3 (CFG_DAT_BYT3)

Bit	Name	Description
7:4	Reserved	Always reads '0'.
3	PRTMAP_EN	<p>Port mapping enable: Selects the method used by the hub to assign port numbers and disable ports.</p> <p>'0' = Standard Mode. Strap options or the following registers are used to define which ports are enabled, and the ports are mapped as Port 'n' on the hub is reported as Port 'n' to the host, unless one of the ports is disabled, then the higher numbered ports are remapped in order to report contiguous port numbers to the host.</p> <p>Register 300Ah: Port Disable For Self-Powered Operation (Reset = 0x00). Register 300Bh: Port Disable For Bus-Powered Operation (Reset = 0x00).</p> <p>'1' = Port map mode. The mode enables remapping via the registers defined below.</p> <p>Register 30FBh: Port Map 12 (Reset = 0x00) Register 30FCh: Port Map 3 (Reset = 0x00)</p>
2:0	Reserved	Always reads '0'.

7.3.5.10 E7h: Non-Removable Device

Bit	Byte Name	Description
7:0	NR_DEVICE	<p>Indicates which port(s) include non-removable devices.</p> <p>'0' = Port is removable '1' = Port is non-removable</p> <p>Informs the host if one of the active ports has a permanent device that is undetachable from the hub. (Note: The device must provide its own descriptor data.)</p> <p>When using the internal default option, the NON_REM[1:0] pins will designate the appropriate ports as being non-removable.</p> <p>Bit 7= Reserved Bit 6= Reserved Bit 5= Reserved Bit 4= Reserved Bit 3= Controls physical port 3 Bit 2= Controls physical port 2 Bit 1= Controls physical port 1 Bit 0= Reserved, always = '0'</p> <p>Note: Bit 1 must be set to a '1' by the firmware for proper identification of the card reader as a non-removable device.</p>

7.3.5.11 E8h: Port Disable For Self-Powered Operation

Bit	Byte Name	Description
7:0	PORT_DIS_SP	<p>Disables 1 or more ports.</p> <p>'0' = Port is available '1' = Port is disabled</p> <p>During self-powered operation this register selects the ports which will be permanently disabled. The ports are unavailable to be enabled or enumerated by a Host Controller. The ports can be disabled in any order since the internal logic will automatically report the correct number of enabled ports to the USB host and will reorder the active ports in order to ensure proper function.</p> <p>Bit 7= Reserved Bit 6= Reserved Bit 5= Reserved Bit 4= Reserved Bit 3= Controls physical port 3 Bit 2= Controls physical port 2 Bit 1= Controls physical port 1 Bit 0= Reserved, always = '0'</p>

7.3.5.12 E9h: Port Disable For Bus-Powered Operation

Bit	Byte Name	Description
7:0	PORT_DIS_BP	<p>Disables 1 or more ports.</p> <p>'0' = Port is available '1' = Port is disabled</p> <p>During self-powered operation, this register selects the ports which will be permanently disabled. The ports are unavailable to be enabled or enumerated by a Host Controller. The ports can be disabled in any order, the internal logic will automatically report the correct number of enabled ports to the USB host and will reorder the active ports in order to ensure proper function.</p> <p>When using the internal default option, the PRT_DIS[1:0] pins will disable the appropriate ports.</p> <p>Bit 7= Reserved Bit 6= Reserved Bit 5= Reserved Bit 4= Reserved Bit 3= Controls physical port 3 Bit 2= Controls physical port 2 Bit 1= Controls physical port 1 Bit 0 is Reserved, always = '0'</p>

7.3.5.13 EAh: Max Power For Self-Powered Operation

Bit	Byte Name	Description
7:0	MAX_PWR_SP	<p>Max Power Self_Powered: Value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a self-powered hub. This value includes the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value also includes the power consumption of a permanently attached peripheral if the hub is configured as a Compound Device, and the embedded peripheral reports 0 mA in its descriptors.</p> <p>Note: The USB 2.0 Specification does not permit this value to exceed 100 mA.</p>

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7.3.5.14 EBh: Max Power For Bus-Powered Operation

Bit	Byte Name	Description
7:0	MAX_PWR_BP	Max Power Bus_Powered: Value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a bus-powered hub. This value includes the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value also includes the power consumption of a permanently attached peripheral if the hub is configured as a Compound Device, and the embedded peripheral reports 0 mA in its descriptors.

7.3.5.15 ECh: Hub Controller Max Current For Self-Powered Operation

Bit	Byte Name	Description
7:0	HC_MAX_C_SP	<p>Hub Controller Max Current Self-Powered: Value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a self-powered hub. This value includes the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value does NOT include the power consumption of a permanently attached peripheral if the hub is configured as a Compound Device.</p> <p>Note: The USB 2.0 Specification does not permit this value to exceed 100 mA.</p> <p>A value of 50 (decimal) indicates 100 mA, which is the default value.</p>

7.3.5.16 EDh: Hub Controller Max Current For Bus-Powered Operation

Bit	Byte Name	Description
7:0	HC_MAX_C_BP	<p>Hub Controller Max Current Bus-Powered: Value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a bus-powered hub. This value will include the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value will NOT include the power consumption of a permanently attached peripheral if the hub is configured as a Compound Device.</p> <p>A value of 50 (decimal) would indicate 100 mA, which is the default value.</p>

7.3.5.17 EEh: Power-On Time

Bit	Byte Name	Description
7:0	PWR_ON_TIME	Power-On Time: The length of time that it takes (in 2 ms intervals) from the time the host initiated power-on sequence begins on a port until power is adequate on that port. System software uses this value to determine how long to wait before accessing a powered-on port.

7.3.5.18 EFh: Boost_Up

Bit	Name	Description
7:2	Reserved	Reserved
1:0	BOOST_IOUT	<p>USB electrical signaling drive strength Boost Bit for the Upstream Port 'A'.</p> <p>'00' = Normal electrical drive strength = No boost '01' = Elevated electrical drive strength = Low (approximately 4% boost) '10' = Elevated electrical drive strength = Medium (approximately 8% boost) '11' = Elevated electrical drive strength = High (approximately 12% boost)</p> <p>Note: "Boost" could result in non-USB Compliant parameters. OEM should use a '00' value unless specific implementation issues require additional signal boosting to correct for degraded USB signalling levels.</p>

7.3.5.19 F0h: Boost_3:0

Bit	Name	Description
7:6	Reserved	Always reads '0'.
5:4	BOOST_IOUT_3	<p>Upstream USB electrical signaling drive strength Boost Bit for Downstream Port '3'.</p> <p>'00' = Normal electrical drive strength = No boost '01' = Elevated electrical drive strength = Low (approximately 4% boost) '10' = Elevated electrical drive strength = Medium (approximately 8% boost) '11' = Elevated electrical drive strength = High (approximately 12% boost)</p>
3:2	BOOST_IOUT_2	<p>Upstream USB electrical signaling drive strength Boost Bit for Downstream Port '2'.</p> <p>'00' = Normal electrical drive strength = No boost '01' = Elevated electrical drive strength = Low (approximately 4% boost) '10' = Elevated electrical drive strength = Medium (approximately 8% boost) '11' = Elevated electrical drive strength = High (approximately 12% boost)</p> <p>Note: "Boost" could result in non-USB Compliant parameters. OEM should use a '00' value unless specific implementation issues require additional signal boosting to correct for degraded USB signalling levels.</p>
1:0	Reserved	Always reads '0'.

7.3.5.20 F1h: Port Swap

Bit	Byte Name	Description
7:0	PRT_SWP	<p>Port Swap: Swaps the Upstream and Downstream USB DP and DM Pins for ease of board routing to devices and connectors.</p> <p>'0' = USB D+ functionality is associated with the DP pin and D- functionality is associated with the DM pin.</p> <p>'1' = USB D+ functionality is associated with the DM pin and D- functionality is associated with the DP pin.</p> <p>Bit 7= Reserved Bit 6= Reserved Bit 5= Reserved Bit 4= Reserved Bit 3= Controls physical port 3 Bit 2= Controls physical port 2 Bit 1= Reserved Bit 0= Controls physical port 0</p>

7.3.5.21 F2h: Port Map 12

Bit	Byte Name	Description																														
7:0	PRTM12	<p>Port map register for ports 1 & 2.</p> <p>When a hub is enumerated by a USB Host Controller, the hub is only permitted to report how many ports it has; the hub is not permitted to select a numerical range or assignment. The Host Controller will number the downstream ports of the hub starting with the number '1', up to the number of ports that the hub reported having.</p> <p>The host's port number is referred to as "logical port number" and the physical port on the hub is the "physical port number". When remapping mode is enabled (see PRTMAP_EN in Register 08h: Configuration Data Byte 3) the hub's downstream port numbers can be remapped to different logical port numbers (assigned by the host).</p> <p>Note: OEM must ensure that contiguous logical port numbers are used, starting from number '1' up to the maximum number of enabled ports; this ensures that the hub's ports are numbered in accordance with the way a host will communicate with the ports.</p> <p>TABLE 7-4: PORT MAP REGISTER FOR PORTS 1 & 2</p> <table> <tr> <td>Bit [7:4]</td><td>'0000'</td><td>Physical Port 2 is Disabled</td></tr> <tr> <td></td><td>'0001'</td><td>Physical Port 2 is mapped to Logical Port 1</td></tr> <tr> <td></td><td>'0010'</td><td>Physical Port 2 is mapped to Logical Port 2</td></tr> <tr> <td></td><td>'0011'</td><td>Physical Port 2 is mapped to Logical Port 3</td></tr> <tr> <td></td><td>'0100' to '1111'</td><td>Illegal; Do Not Use</td></tr> <tr> <td>Bit [3:0]</td><td>'0000'</td><td>Physical Port 1 is Disabled</td></tr> <tr> <td></td><td>'0001'</td><td>Physical Port 1 is mapped to Logical Port 1</td></tr> <tr> <td></td><td>'0010'</td><td>Physical Port 1 is mapped to Logical Port 2</td></tr> <tr> <td></td><td>'0011'</td><td>Physical Port 1 is mapped to Logical Port 3</td></tr> <tr> <td></td><td>'0100' to '1111'</td><td>Illegal; Do Not Use</td></tr> </table>	Bit [7:4]	'0000'	Physical Port 2 is Disabled		'0001'	Physical Port 2 is mapped to Logical Port 1		'0010'	Physical Port 2 is mapped to Logical Port 2		'0011'	Physical Port 2 is mapped to Logical Port 3		'0100' to '1111'	Illegal; Do Not Use	Bit [3:0]	'0000'	Physical Port 1 is Disabled		'0001'	Physical Port 1 is mapped to Logical Port 1		'0010'	Physical Port 1 is mapped to Logical Port 2		'0011'	Physical Port 1 is mapped to Logical Port 3		'0100' to '1111'	Illegal; Do Not Use
Bit [7:4]	'0000'	Physical Port 2 is Disabled																														
	'0001'	Physical Port 2 is mapped to Logical Port 1																														
	'0010'	Physical Port 2 is mapped to Logical Port 2																														
	'0011'	Physical Port 2 is mapped to Logical Port 3																														
	'0100' to '1111'	Illegal; Do Not Use																														
Bit [3:0]	'0000'	Physical Port 1 is Disabled																														
	'0001'	Physical Port 1 is mapped to Logical Port 1																														
	'0010'	Physical Port 1 is mapped to Logical Port 2																														
	'0011'	Physical Port 1 is mapped to Logical Port 3																														
	'0100' to '1111'	Illegal; Do Not Use																														

7.3.5.22 F3h: Port Map 3

Bit	Byte Name	Description																														
7:0	PRTM3	<p>Port map register for port 3.</p> <p>When a hub is enumerated by a USB Host Controller, the hub is only permitted to report how many ports it has; the hub is not permitted to select a numerical range or assignment. The Host Controller will number the downstream ports of the hub starting with the number '1', up to the number of ports that the hub reported having.</p> <p>The host's port number is referred to as "logical port number" and the physical port on the hub is the "physical port number". When remapping mode is enabled (see PRTMAP_EN in Register 08h: Configuration Data Byte 3) the hub's downstream port numbers can be remapped to different logical port numbers (assigned by the host).</p> <p>Note: OEM must ensure that contiguous logical port numbers are used, starting from number '1' up to the maximum number of enabled ports; this ensures that the hub's ports are numbered in accordance with the way a host will communicate with the ports.</p>																														
TABLE 7-5: PORT MAP REGISTER FOR PORT 3 <table> <tr> <td>Bit [7:4]</td><td>'0000'</td><td>Reserved</td></tr> <tr> <td></td><td>'0001'</td><td>Reserved</td></tr> <tr> <td></td><td>'0010'</td><td>Reserved</td></tr> <tr> <td></td><td>'0011'</td><td>Reserved</td></tr> <tr> <td></td><td>'0100' to '1111'</td><td>Illegal; Do Not Use</td></tr> <tr> <td>Bit [3:0]</td><td>'0000'</td><td>Physical Port 3 is Disabled</td></tr> <tr> <td></td><td>'0001'</td><td>Physical Port 3 is mapped to Logical Port 1</td></tr> <tr> <td></td><td>'0010'</td><td>Physical Port 3 is mapped to Logical Port 2</td></tr> <tr> <td></td><td>'0011'</td><td>Physical Port 3 is mapped to Logical Port 3</td></tr> <tr> <td></td><td>'0100' to '1111'</td><td>Illegal; Do Not Use</td></tr> </table>			Bit [7:4]	'0000'	Reserved		'0001'	Reserved		'0010'	Reserved		'0011'	Reserved		'0100' to '1111'	Illegal; Do Not Use	Bit [3:0]	'0000'	Physical Port 3 is Disabled		'0001'	Physical Port 3 is mapped to Logical Port 1		'0010'	Physical Port 3 is mapped to Logical Port 2		'0011'	Physical Port 3 is mapped to Logical Port 3		'0100' to '1111'	Illegal; Do Not Use
Bit [7:4]	'0000'	Reserved																														
	'0001'	Reserved																														
	'0010'	Reserved																														
	'0011'	Reserved																														
	'0100' to '1111'	Illegal; Do Not Use																														
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	'0010'	Physical Port 3 is mapped to Logical Port 2																														
	'0011'	Physical Port 3 is mapped to Logical Port 3																														
	'0100' to '1111'	Illegal; Do Not Use																														

7.3.5.23 F4h-FBh: Reserved

Byte	Byte Name	Description
7:0	Reserved	Reserved.

7.3.5.24 FCh-FFh: Non-volatile Storage Signature

Byte	Byte Name	String	Description
3:0	NVSTORE_SIG	"ATA2"	This signature is used to verify the validity of the data in the configuration area. The signature must be set to 'ATA2' for USB2649/USB2649I.

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7.3.6 IN-CIRCUIT EEPROM PROGRAMMING

The EEPROM can be programmed via automatic testing test equipment (ATE) by pulling nRESET low which tri-states the device's EEPROM interface and allows an external source to program the EEPROM.

7.4 Default Configuration Option:

The Microchip device can be configured via its internal default configuration. Please see [Section 7.3.2, "EEPROM Data Descriptor"](#) for specific details on how to enable default configuration. Please refer to [Table 7-1](#) for the internal default values that are loaded when this option is selected.

7.5 Reset

There are two different resets that the device experiences. One is a hardware reset (either from the internal POR reset circuit or via the nRESET pin) and the second is a USB Bus Reset.

7.5.1 INTERNAL POR HARDWARE RESET

All reset timing parameters are ensured by design.

7.5.2 EXTERNAL HARDWARE NRESET

A valid hardware reset is defined as assertion of nRESET for a minimum of 1 μ s after all power supplies are within operating range. While reset is asserted, the device (and its associated external circuitry) consumes less than 500 μ A of current from the upstream USB power source.

Assertion of nRESET (external pin) causes the following:

1. All downstream ports are disabled, and PRTCTL power to downstream devices is removed.
2. The PHYs are disabled, and the differential pairs will be in a high-impedance state.
3. All transactions immediately terminate; no states are saved.
4. All internal registers return to the default state (in most cases, 00h).
5. The external crystal oscillator is halted.
6. The PLL is halted.

7.5.2.1 nRESET for EEPROM Configuration

FIGURE 7-1: NRESET TIMING FOR EEPROM MODE

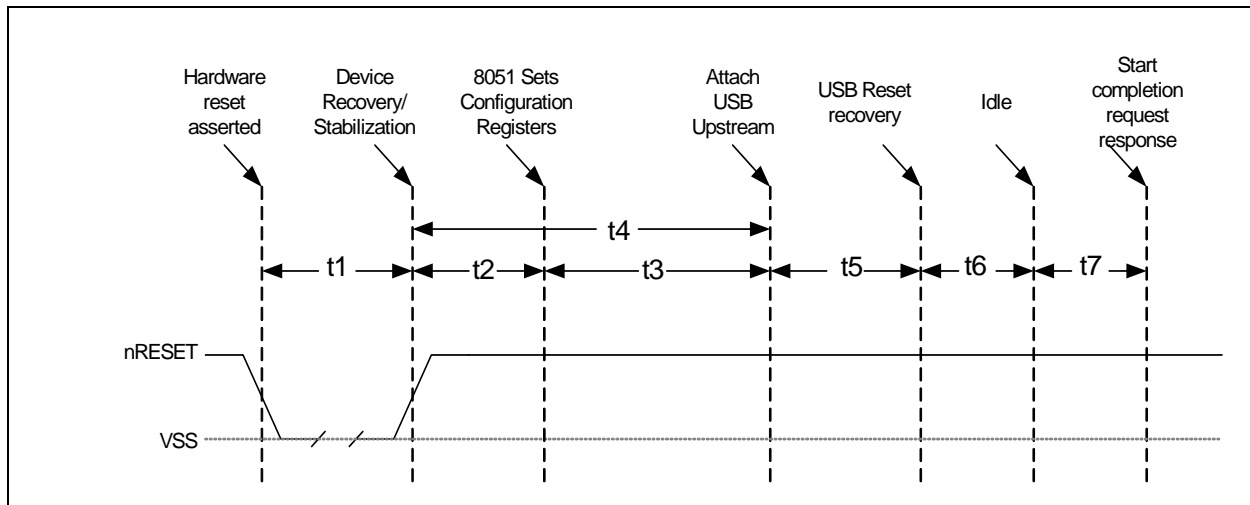


TABLE 7-6: NRESET TIMING FOR EEPROM MODE

Name	Description	MIN	TYP	MAX	Units
t1	nRESET asserted.	1			μsec
t2	Device recovery/stabilization.			500	μsec
t3	8051 programs device configuration		20	50	msec
t4	USB attach (See Note).			100	msec
t5	Host acknowledges attach and signals USB reset.	100			msec
t6	USB idle.		Undefined		msec
t7	Completion time for requests (with or without data stage).			5	msec

Note: All power supplies must have reached the operating levels mandated in [Section 9.0, "DC Parameters," on page 41](#), prior to (or coincident with) the assertion of nRESET.

7.5.3 USB BUS RESET

In response to the upstream port signaling a reset to the device, the device does the following:

Note: The device does not propagate the upstream USB reset to downstream devices.

1. Sets default address to '0'.
2. Sets configuration to: Unconfigured.
3. Negates PRTCTL[3:2] to all downstream ports.
4. Clears all TT buffers.
5. Moves device from suspended to active (if suspended).
6. Complies with Section 11.10 of the USB 2.0 Specification for behavior after completion of the reset sequence.

The host then configures the device and the device's downstream port devices in accordance with the USB 2.0 Specification.

8.0 PIN RESET STATES

FIGURE 8-1: PIN RESET STATES

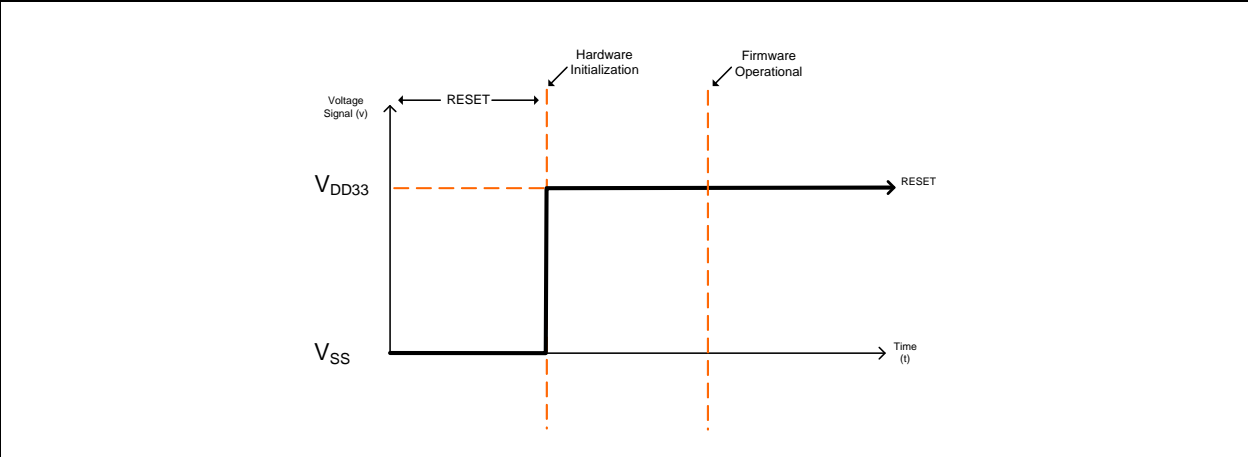


TABLE 8-1: LEGEND FOR PIN RESET STATES TABLE

Symbol	Description
Y	Hardware enables function
0	Output low
1	Output high
--	Hardware disables function
Z	Hardware disables output driver (high impedance)
PU	Hardware enables pull-up
PD	Hardware enables pull-down
HW	Hardware controls function, but state is protocol dependent
(FW)	Firmware controls function through registers
VDD	Hardware supplies power through pin, applicable only to CARD_PWR pin
none	Hardware disables pad

8.1 Pin Reset States

TABLE 8-2: USB2649/USB2649I PIN RESET STATES

Pin	Pin Name	Reset State			
		Function	Output	PU/PD	Input
1	USBDN_DM2	USBDN_DM2	0	PD	--
2	USBDN_DP2	USBDN_DP2	0	PD	--
3	USBDN_DM3	USBDN_DM3	0	PD	--
4	USBDN_DP3	USBDN_DP3	0	PD	--
6	PRTCTL2	PRTCTL	0	--	--

TABLE 8-2: USB2649/USB2649I PIN RESET STATES (CONTINUED)

Pin	Pin Name	Reset State			
		Function	Output	PU/PD	Input
7	PRTCTL3	PRTCTL	0	--	--
8	SPI_CE_n	SPI_CE_n	1	--	--
9	SPI_CLK	SPI_CLK	0	--	--
10	SPI_DO / SPI_SPD_SEL	SPI_SPD_SEL	Z	PD	Y
11	SPI_DI	SPI_DI	Z	PD	Y
13	xD_D4 / SD_WP / MS_SCLK	none	0	--	--
14	SD_nCD	none	Z	PU	Y
17	xD_D3 / SD_D1 / MS_D5	none	Z	--	--
18	xD_D2 / SD_D0 / MS_D4	none	Z	--	--
19	xD_D1 / SD_D7 / MS_D6	none	Z	--	--
20	xD_D0 / SD_D6 / MS_D7	none	Z	--	--
21	xD_nWP / SD_CLK / MS_BS	none	Z	--	--
22	xD_nWE	none	Z	--	--
23	xD_ALE / SD_D5 / MS_D1	none	Z	--	--
24	xD_CLE / SD_CMD / MS_D0	none	Z	--	--
26	xD_nCE	none	Z	--	--
27	xD_nRE	none	Z	--	--
28	xD_nB/R	none	Z	--	--
29	xD_nCD	none	Z	PU	Y
30	xD_D7 / SD_D4 / MS_D2	none	Z	--	--
31	MS_INS	none	Z	PU	Y
32	xD_D6 / SD_D3 / MS_D3	none	Z	--	--
33	xD_D5 / SD_D2	none	Z	--	--
35	CARD_PWR	none	Z	--	--
37	LED / TXD	none	0	--	--
38	nRESET	nRESET	Z	--	Y
39	VBUS_DET	VBUS_DET	Z	--	Y
40	TEST	TEST	Z	--	Y

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TABLE 8-2: USB2649/USB2649I PIN RESET STATES (CONTINUED)

		Reset State			
Pin	Pin Name	Function	Output	PU/PD	Input
42	USB+	USB+	Z	--	--
43	USB-	USB-	Z	--	--
44	XTAL2				
45	XTAL1 (CLKIN)				
47	RBIAS				

9.0 DC PARAMETERS

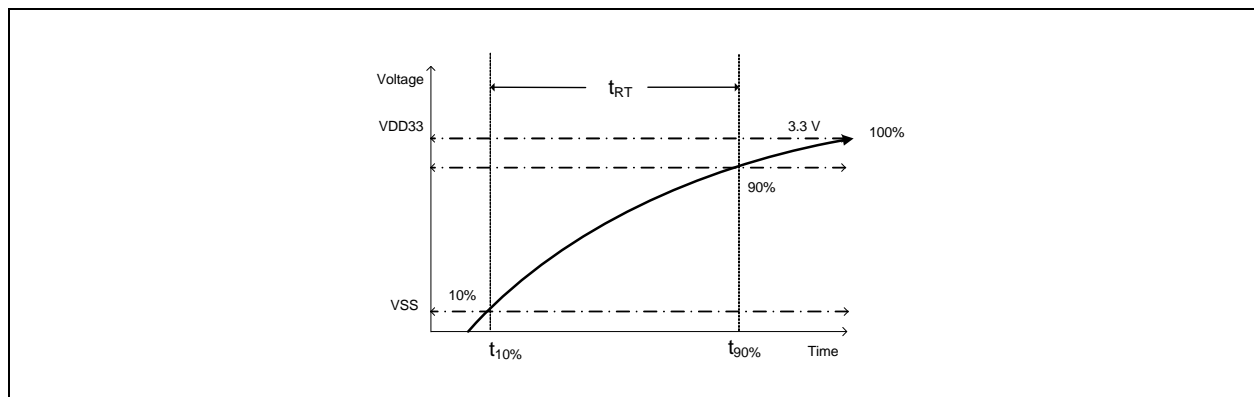
9.1 Maximum Ratings

Parameter	Symbol	MIN	MAX	Units	Comments
Storage Temperature	T _{STOR}	-55	150	°C	
Lead Temperature			325	°C	Soldering < 10 seconds
3.3 V supply voltage	V _{DD33}	-0.5	4.0	V	
Voltage on USB+ and USB- pins		-0.5	(3.3 V supply voltage + 2) ≤ 6	V	
Voltage on CRD_PWR		-0.5	V _{DD33} + 0.3	V	When internal power FET operation of these pins are enabled, these pins may be simultaneously shorted to ground or any voltage up to 3.63 V indefinitely, without damage to the device as long as V _{DD33} is less than 3.63 V and T _A is less than 70°C.
Voltage on any signal pin		-0.5	V _{DD33} + 0.3	V	
Voltage on XTAL1		-0.5	3.6	V	
Voltage on XTAL2		-0.5	2.0	V	

Note 9-1 Stresses above the specified parameters may cause permanent damage to the device. This is a stress rating only. Functional operation of the device at any condition above those indicated in the operation sections of this specification is not implied.

Note 9-2 When powering this device from laboratory or system power supplies the Absolute Maximum Ratings must not be exceeded or device failure can result. Some power supplies exhibit voltage spikes on their outputs when the AC power is switched on or off. In addition, voltage transients on the AC power line may appear on the DC output. When this possibility exists, a clamp circuit should be used.

FIGURE 9-1: SUPPLY RISE TIME MODELS



USB2649/USB2649I

9.2 Operating Conditions

Parameter	Symbol	MIN	MAX	Units	Comments
Operating Temperature	T_A	0	70	°C	Ambient temperature in still air.
3.3 V supply voltage	V_{DD33}	3.0	3.6	V	A 3.3 V regulator with an output tolerance of 1% must be used if the output of the internal power FETs must support a 5% tolerance.
3.3 V supply rise time	t_{RT}	0	400	μs	(Figure 9-1)
Voltage on USB+ and USB- pins		-0.3	5.5	V	If any 3.3 V supply voltage drops below 3.0 V, then the MAX becomes: (3.3 V supply voltage) + 0.5 ≤ 5.5
Voltage on any signal pin		-0.3	V_{DD33}	V	
Voltage on XTAL1		-0.3	2.0	V	
Voltage on XTAL2		-0.3	2.0	V	

9.3 DC Electrical Characteristics

Parameter	Symbol	MIN	TYP	MAX	Units	Comments
I, IPU, IPD Type Input Buffer						
Low Input Level	V _{ILI}	2.0		0.8	V	TTL Levels
High Input Level	V _{IHI}			V		
Pull Down	PD	72	μA			
Pull Up	PU	58	μA			
IS Type Input Buffer						
Low Input Level	V _{ILI}	2.0		0.8	V	TTL Levels
High Input Level	V _{IHI}			V		
Hysteresis	V _{HYSI}	420	mV			
ICLK Input Buffer						
Low Input Level	V _{ILCK}	1.4		0.5	V	V _{IN} = 0 to V _{DD33}
High Input Level	V _{IHCK}			V		
Input Leakage	I _{IL}	-10	+10	μA		
Input Leakage						
(All I and IS buffers)						
Low Input Leakage	I _{IL}	-10		+10	μA	V _{IN} = 0
High Input Leakage	I _{IH}	-10		+10	μA	V _{IN} = V _{DD33}

Parameter	Symbol	MIN	TYP	MAX	Units	Comments
O12 Type Buffer						
Low Output Level	V_{OL}			0.4	V	$I_{OL} = 12 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
High Output Level	V_{OH}	$V_{DD33} - 0.4$			V	$I_{OH} = -12 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
Output Leakage	I_{OL}	-10		+10	μA	$V_{IN} = 0 \text{ to } V_{DD33}$ (Note 9-3)
I/O12, I/O12PU & I/O12PD Type Buffer						
Low Output Level	V_{OL}			0.4	V	$I_{OL} = 12 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
High Output Level	V_{OH}	$V_{DD33} - 0.4$			V	$I_{OH} = -12 \text{ mA @ } V_{DD33} = 3.3 \text{ V}$
Output Leakage	I_{OL}	-10		+10	μA	$V_{IN} = 0 \text{ to } V_{DD33}$ (Note 9-3)
Pull Down	PD		72		μA	
Pull Up	PU		58		μA	
IO-U						(Note 9-4)
I-R						(Note 9-5)
Integrated Power FET Set to 100 mA						
Output Current (Note 9-6)	I_{OUT}	100			mA	$V_{dropFET} = 0.22 \text{ V}$
Short Circuit Current Limit	I_{SC}			140	mA	$V_{outFET} = 0 \text{ V}$
On Resistance (Note 9-6)	$R_{DS(on)}$			2.1	Ω	$I_{FET} = 70 \text{ mA}$
Output Voltage Rise Time	t_{DSON}			800	μs	$C_{LOAD} = 10 \mu\text{F}$
Integrated Power FET Set to 200 mA						
Output Current (Note 9-6)	I_{OUT}	200			mA	$V_{dropFET} = 0.46 \text{ V}$
Short Circuit Current Limit	I_{SC}			181	mA	$V_{outFET} = 0 \text{ V}$
On Resistance (Note 9-6)	$R_{DS(on)}$			2.1	Ω	$I_{FET} = 70 \text{ mA}$
Output Voltage Rise Time	t_{DSON}			800	μs	$C_{LOAD} = 10 \mu\text{F}$

USB2649/USB2649I

Parameter	Symbol	MIN	TYP	MAX	Units	Comments
USB2649						
Supply Current Unconfigured						
Hi-Speed Host	$I_{CCINTHS}$		65	70	mA	
Full Speed Host	$I_{CCINITFS}$		60	65	mA	
Supply Current Active	I_{CC}		280	300	mA	
Supply Current Suspend	I_{CSBY}		420	550	μ A	
Supply Current Reset	I_{RST}		205	325	μ A	
USB2649i						
Supply Current Unconfigured						
Hi-Speed Host	$I_{CCINTHS}$		65	80	mA	
Full Speed Host	$I_{CCINITFS}$		60	75	mA	
Supply Current Active	I_{CC}		280	315	mA	
Supply Current Suspend	I_{CSBY}		420	650	μ A	
Supply Current Reset	I_{RST}		205	425	μ A	

Note 9-3 Output leakage is measured with the current pins in high impedance.

Note 9-4 See the USB 2.0 Specification, Chapter 7, for USB DC electrical characteristics

Note 9-5 RBIAS is a 3.3 V tolerant analog pin.

Note 9-6 Output current range is controlled by program software. The software disables the FET during short circuit condition.

9.4 Capacitance $T_A = 25^\circ\text{C}$; $f_c = 1\text{ MHz}$; $V_{DD33} = 3.3\text{ V}$

TABLE 9-1: PIN CAPACITANCE

Parameter	Symbol	Limits			Unit	Test Condition
		MIN	TYP	MAX		
Clock Input Capacitance	C_{XTAL}			2	pF	All pins (except USB pins and pins under test) are tied to AC ground.
Input Capacitance	C_{IN}			10	pF	
Output Capacitance	C_{OUT}			20	pF	

10.0 AC SPECIFICATIONS

10.1 Oscillator/Crystal

Parallel Resonant, Fundamental Mode, 24 MHz ± 350 ppm.

FIGURE 10-1: TYPICAL CRYSTAL CIRCUIT

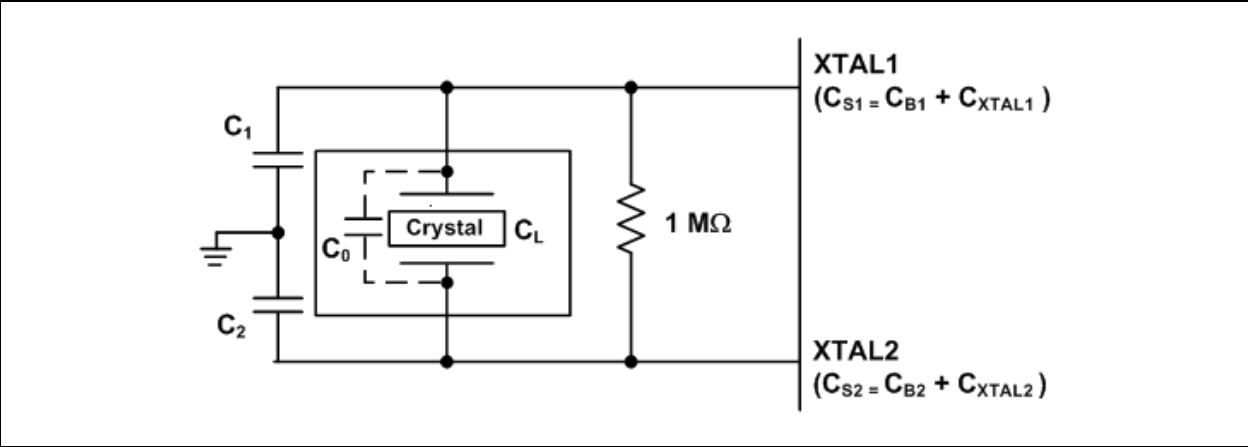


TABLE 10-1: CRYSTAL CIRCUIT LEGEND

Symbol	Description	In Accordance With
C ₀	Crystal shunt capacitance	Crystal manufacturer's specification (See Note 10-1)
C _L	Crystal load capacitance	
C _B	Total board or trace capacitance	OEM board design
C _S	Stray capacitance	Microchip IC and OEM board design
C _{XTAL}	XTAL pin input capacitance	Microchip IC
C ₁	Load capacitors installed on OEM board	Calculated values based on Figure 10-2, "Capacitance Formulas" (See Note 10-2)
C ₂		

FIGURE 10-2: CAPACITANCE FORMULAS

$$C_1 = 2 \times (C_L - C_0) - C_{S1}$$
$$C_2 = 2 \times (C_L - C_0) - C_{S2}$$

Note 10-1 C₀ is usually included (subtracted by the crystal manufacturer) in the specification for C_L and should be set to '0' for use in the calculation of the capacitance formulas in Figure 10-2, "Capacitance Formulas". However, the OEM PCB itself may present a parasitic capacitance between XTAL1 and XTAL2. For an accurate calculation of C₁ and C₂, take the parasitic capacitance between traces XTAL1 and XTAL2 into account.

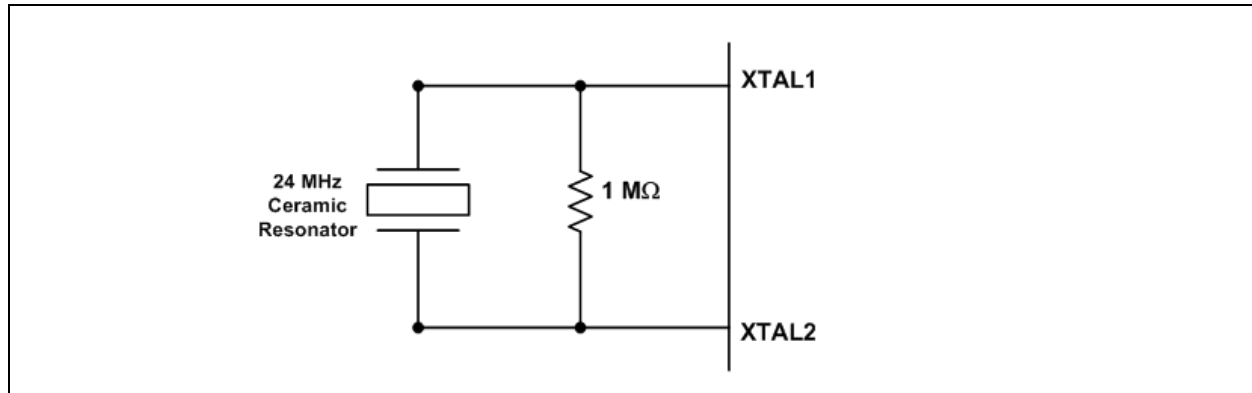
Note 10-2 Each of these capacitance values is typically approximately 18 pF.

USB2649/USB2649I

10.2 Ceramic Resonator

24 MHz \pm 350 ppm

FIGURE 10-3: CERAMIC RESONATOR USAGE WITH MICROCHIP IC



10.3 External Clock

50% Duty cycle \pm 10%, 24 MHz \pm 350 ppm, Jitter < 100 ps rms.

The external clock is recommended to conform to the signaling level designated in the JESD76-2 specification on 1.8 V CMOS Logic. XTAL2 should be treated as a no connect.

10.3.1 I²C EEPROM

Frequency is fixed at 58.6 kHz \pm 20%

10.3.2 USB 2.0

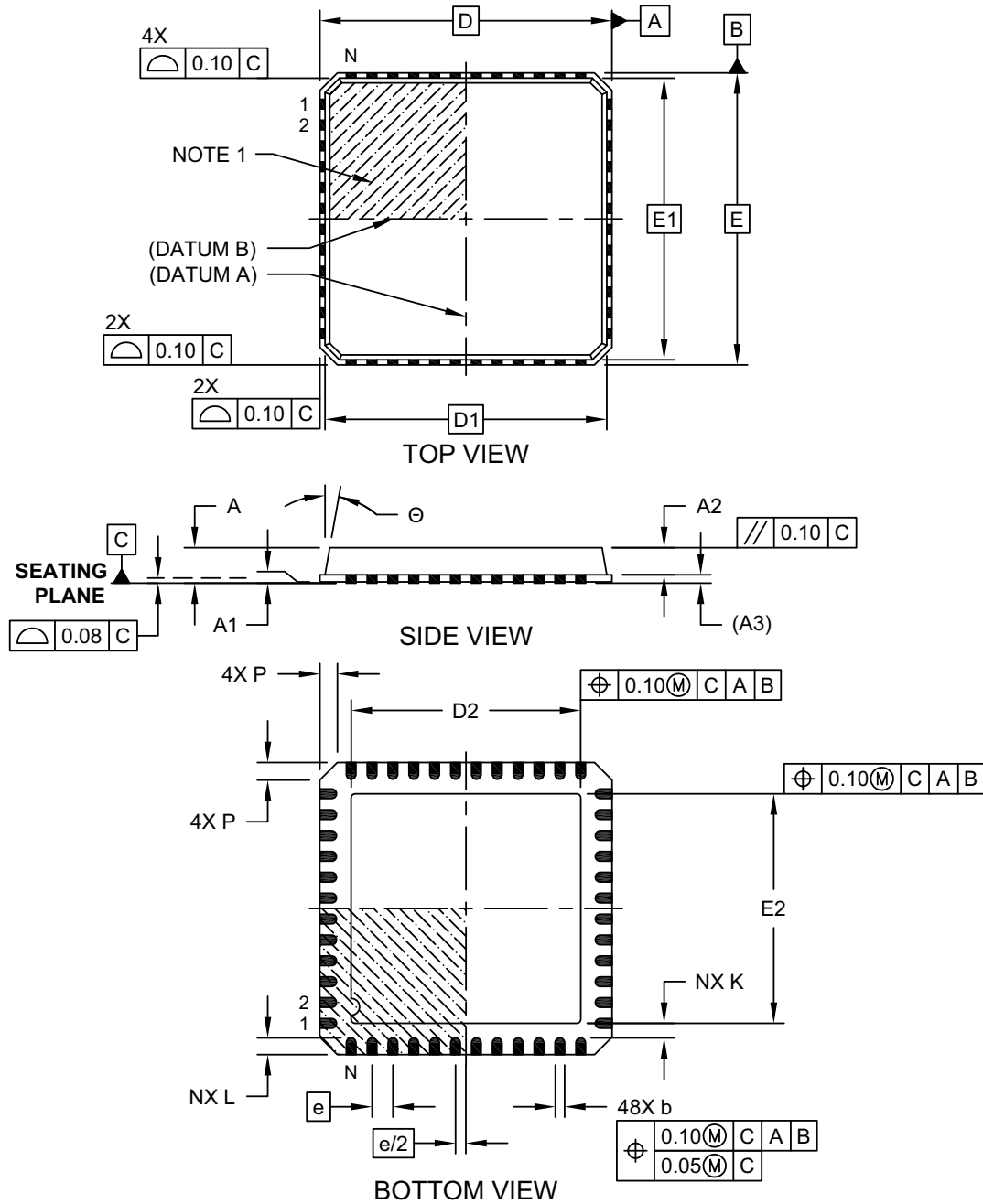
The Microchip device conforms to all voltage, power, and timing characteristics and specifications as set forth in the USB 2.0 Specification. Please refer to the USB 2.0 Specification for more information.

11.0 PACKAGE OUTLINE

FIGURE 11-1: USB2649/USB2649I 48-PIN QFN, 7 X 7 MM BODY, 0.5 MM PITCH

**48-Lead Plastic Quad Flat, No Lead Package (RS) - 7x7 mm Body [VQFN]
With Exposed Pad; Punch Singulated (AIS Package HZH)**

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



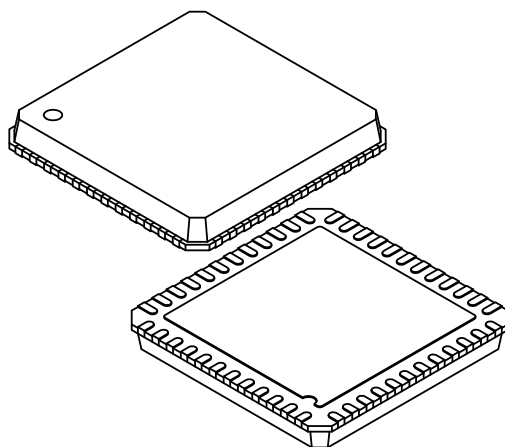
Microchip Technology Drawing C04-223C Sheet 1 of 2

USB2649/USB2649I

FIGURE 11-1: USB2649/USB2649I 48-PIN QFN, 7 X 7 MM BODY, 0.5 MM PITCH (CONTINUED)

48-Lead Plastic Quad Flat, No Lead Package (RS) - 7x7 mm Body [VQFN] With Exposed Pad; Punch Singulated (AIS Package HZH)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Terminals	N	48		
Pitch	e	0.50 BSC		
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	0.01	0.05
Mold Cap Height	A2	0.60	0.65	0.70
Terminal Thickness	(A3)	0.20 REF		
Overall Width	E	7.00 BSC		
Molded Top Width	E1	6.75 BSC		
Exposed Pad Width	E2	(See Exposed Pad Variations)		
Overall Length	D	7.00 BSC		
Molded Top Length	D1	6.75 BSC		
Exposed Pad Length	D2	(See Exposed Pad Variations)		
Corner Chamfer	P	0.24	0.42	0.60
Terminal Width	b	0.18	0.23	0.30
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-
Mold Draft Angle	θ	0°	-	12°

Exposed Pad Variations						
Symbol	D2			E2		
Variant	MIN	NOM	MAX	MIN	NOM	MAX
C	4.00	4.10	4.20	4.00	4.10	4.20
G	5.00	5.10	5.20	5.00	5.10	5.20
H	5.20	5.30	5.40	5.20	5.30	5.40
K	5.40	5.50	5.60	5.40	5.50	5.60

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is punch singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

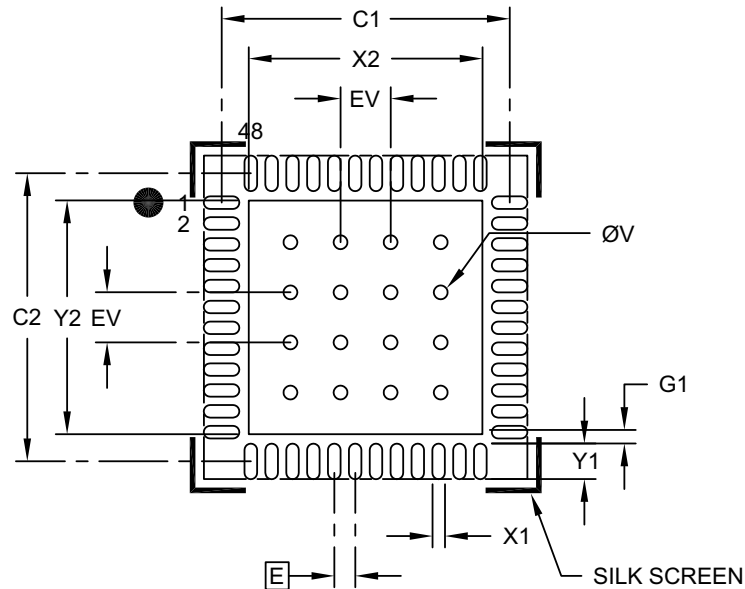
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-223C Sheet 2 of 2

FIGURE 11-1: USB2649/USB2649I 48-PIN QFN, 7 X 7 MM BODY, 0.5 MM PITCH (CONTINUED)

**48-Lead Plastic Quad Flat, No Lead Package (RS) - 7x7 mm Body [VQFN]
With Exposed Pad; Punch Singulated (AIS Package HZH)**

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	X2	See Center Pad Variations		
Optional Center Pad Length	Y2	See Center Pad Variations		
Contact Pad Spacing	C1		6.90	
Contact Pad Spacing	C2		6.90	
Contact Pad Width (X48)	X1			0.30
Contact Pad Length (X48)	Y1			0.85
Contact Pad to Center Pad (X48)	G1	0.20		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Center Pad Variations						
Symbol	X2			Y2		
Variant	MIN	NOM	MAX	MIN	NOM	MAX
C			4.20			4.20
G			5.20			5.20
H			5.40			5.40
K			5.60			5.60

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2223B

Note: This product is a variant 'C'.

USB2649/USB2649I

APPENDIX A: DATA SHEET REVISION HISTORY

TABLE A-1: REVISION HISTORY

Revision	Section/Figure/Entry	Correction
DS00001949A (06-08-15)	Replaces previous SMSC version Rev. 2.1 (06-29-09)	

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USB2649/USB2649I

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To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>		<u>[X]</u>	-	<u>XXX</u>	-	<u>[X]</u>
Device		Temperature Range		Package	Tape and Reel Option	
Device:	USB2649					
Temperature Range:	Blank	=	0°C to +70°C (Commercial)			
	I	=	-40°C to +85°C (Industrial)			
Package:	HZH	=	48-pin QFN			
Tape and Reel Option:	Not available					

Examples:
USB2649-HZH
48-pin QFN RoHS Compliant package, Commercial Temp, Tray
USB2649I-HZH
48-pin QFN RoHS Compliant package, Industrial Temp, Tray

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